



IS66WVH128M8EALL/BLL

IS67WVH128M8EALL/BLL

1Gb

1.8V/3.0V HYPERRAM (x8)

ADVANCED DATA SHEET

1Gb HyperRAM™ (x8)

ADVANCED INFORMATION

Overview

The IS66/67WVH128M8EALL/BLL are DDP (Dual Die Package) memory device containing 2 units of 512Mb Pseudo Static Random Access Memory, organized as 128M words by 8 bits. The device supports a HyperBus interface, Very Low Signal Count (Address, Command, and data through 8 DQ pins), Hidden Refresh Operation, and Automotive Temperature Operation, designed especially for Mobile and Automotive applications.

Key Features

HyperBus™ Low Signal Count Interface

- 1.7 to 2.0V (1.8V typ.) and 2.7 to 3.6V (3.0 V typ.) interface support
- Single-ended clock (CK) – 11 bus signals
- Optional differential clock (CK, CK#) – 12 bus signals
- Chip Select (CS#)
- 8-bit data bus (DQ [7:0])
- Hardware reset (RESET#)
- Bidirectional Read-Write Data Strobe (RWDS)
 - Output during read transactions as Read Data Strobe
 - Input during write transactions as Write Data Mask

High Performance

- 250MHz (1.8V)/200MHz(3.0V) maximum clock rate
- Double-Data Rate (DDR) - two data transfers per clock
- Data throughput up to 500MBps(1.8V)/400MBps(3.0V)

- Configurable Burst Characteristics
 - Wrapped burst lengths:
 - 16 bytes (8 clocks)
 - 32 bytes (16 clocks)
 - 64 bytes (32 clocks)
 - 128 bytes (64 clocks)
 - Linear burst until the end of die boundary
 - Hybrid burst - one wrapped burst followed by linear burst
 - Wrapped or linear burst type selected in each transaction
- Configurable output drive strength
- Power modes
 - Hybrid Sleep mode
 - Deep Power Down
- Memory array refresh
 - Partial array (1/8, 1/4, 1/2, and so on)
 - Full array
- Temperature Grade
 - Industrial: -40°C to +85°C
 - Auto (A1) Grade: -40°C to +85°C
 - Auto (A2) Grade: -40°C to +105°C
- Package
 - 24- ball FBGA
 - Green Package (RoHS Compliant, Halogen-Free) and TSCA Compliant

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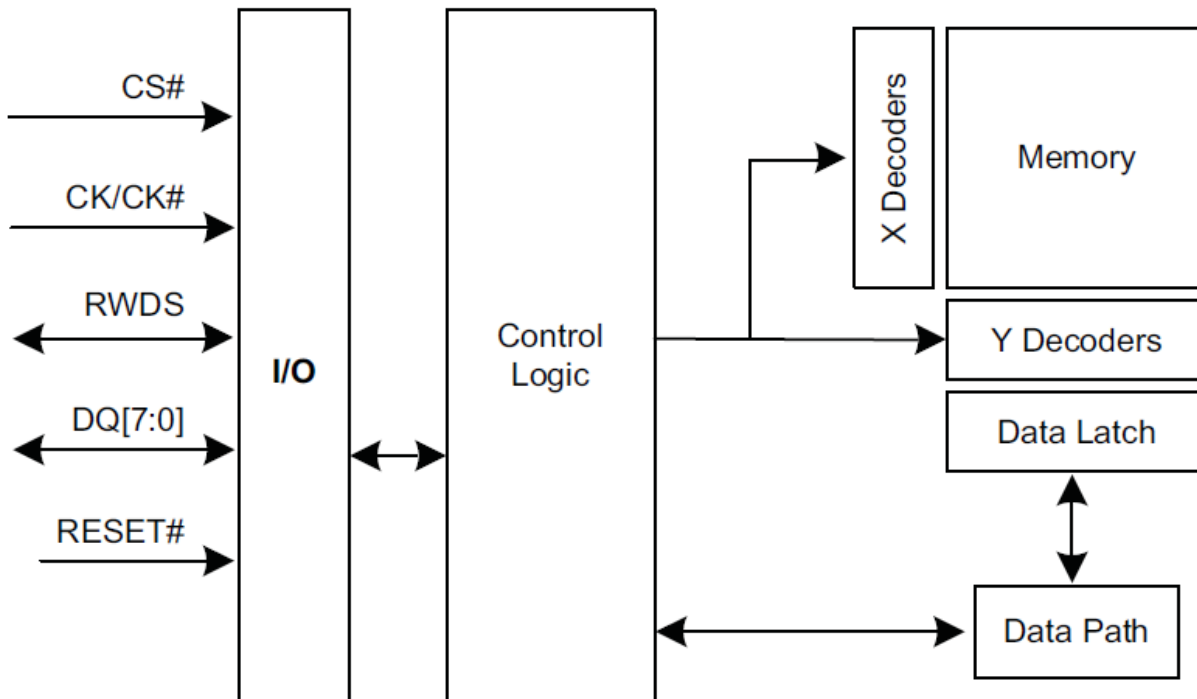
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Performance Summary

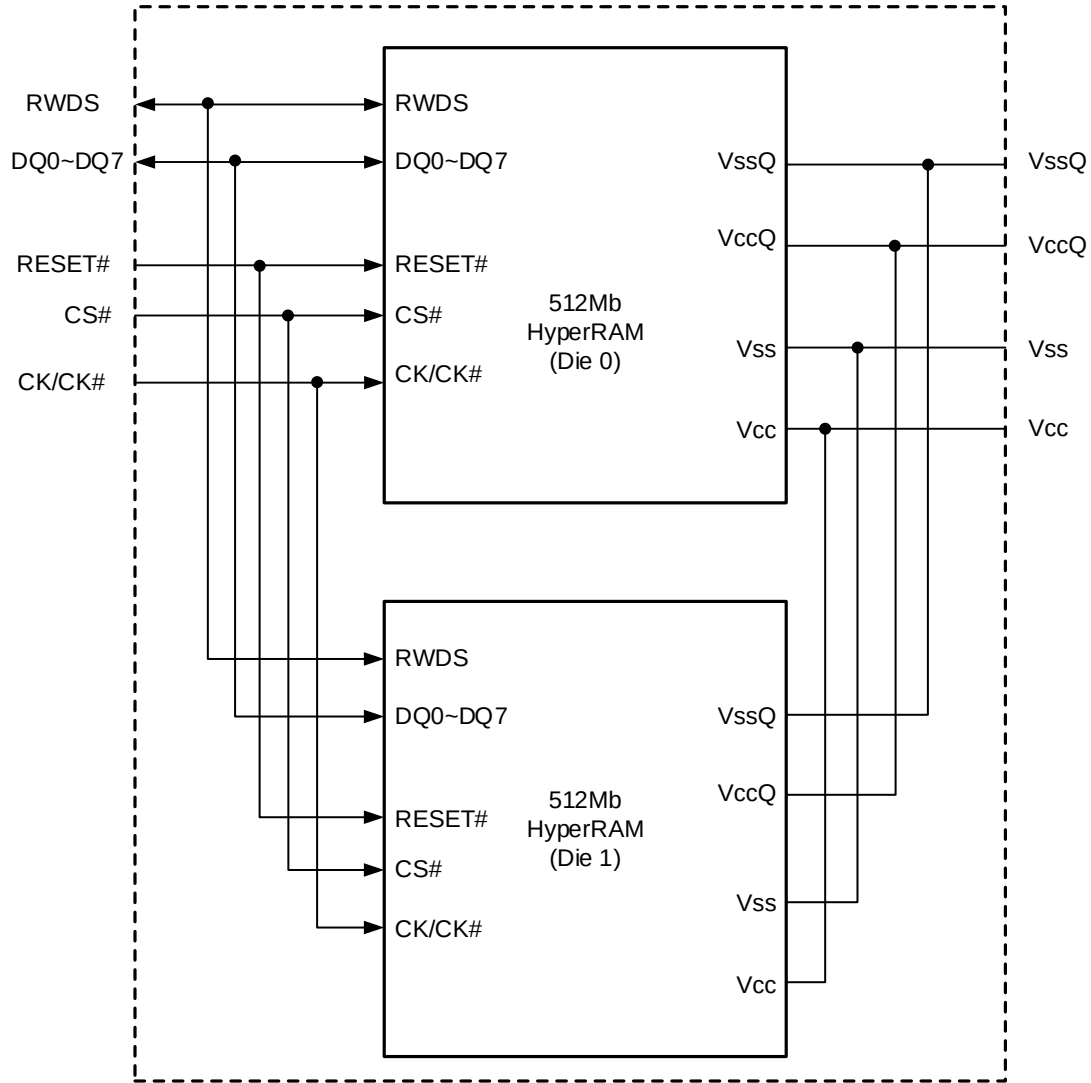
Read Transaction Timings	
Maximum Clock Rate (1.8V)	250 MHz
Maximum Access Time (1.8V)	28ns
Maximum Clock Rate (3.0V)	200 MHz
Maximum Access Time (3.0V)	35 ns

Maximum Current Consumption		
V _{CC} Active Read Current	1.8V, 250MHz	80 mA
	3V, 200MHz	70 mA
V _{CC} Active Write Current	1.8V, 250MHz	80 mA
	3V, 200MHz	70 mA
Standby (CS# = High, 1.8V, 105 °C)		3600 uA
Standby (CS# = High, 3V, 105 °C)		3600 uA
Deep power down (1.8V, 105 °C)		100 uA
Deep power down (3V, 105 °C)		160 uA

Logic Block Diagram



Package Block Diagram



Notes:

1. Address for Die 0 is 01FFFFFFh ~ 00000000h, and for Die 1 is 03FFFFFF~02000000h.
2. Burst read and write operations cannot cross die boundary.



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1. General Description

The ISSI 1Gbit HyperRAM™ device is a high-speed CMOS, self-refresh Dynamic RAM (DRAM), with a HyperBus. The Random Access Memory (RAM) array uses dynamic cells that require periodic refresh. Refresh control logic within the device manages the refresh operations on the RAM array when the memory is not being actively read or written by the HyperBus interface master (host). Since the host is not required to manage any refresh operations, the DRAM array appears to the host as though the memory uses static cells that retain data without refresh. Hence, the memory can also be described as Pseudo Static RAM (PSRAM).

Because the DRAM cells cannot be refreshed during a read or write transaction, there is a requirement that the host not perform read or write burst transfers that are long enough to block the necessary internal logic refresh operations when they are needed. The host is required to limit the duration of transactions and allow additional initial access latency, at the beginning of a new transaction, if the memory indicates a refresh operation is needed.

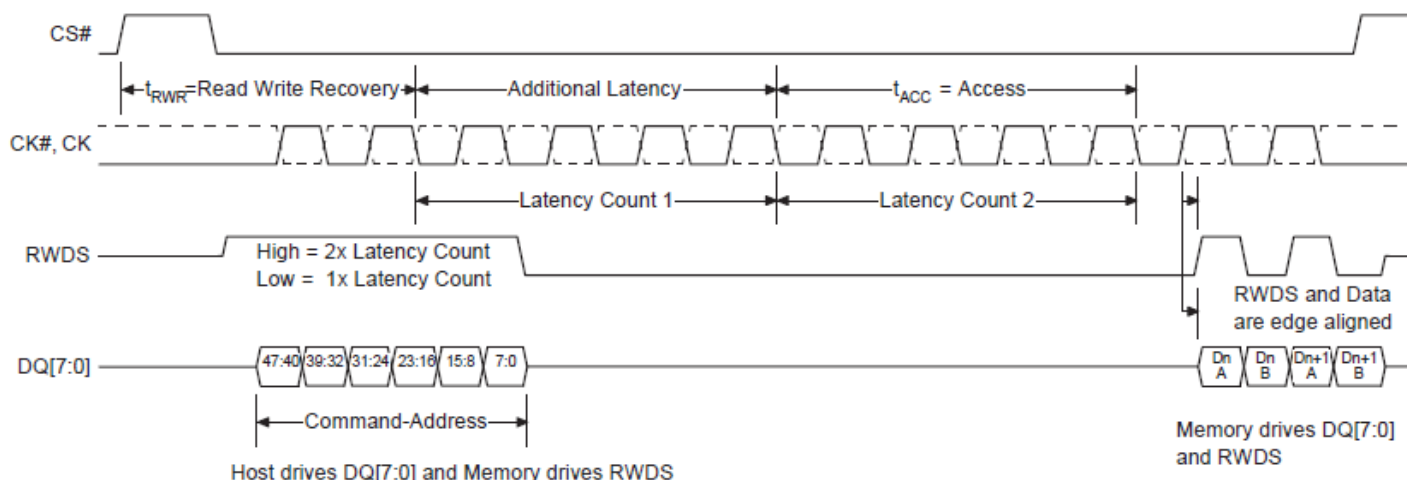
1.1 HYPERBUS™ interface

HyperBus is a low signal count, Double Data Rate (DDR) interface, that achieves high speed read and write throughput. The DDR protocol transfers two 8-bit data words per clock cycle on the DQ [7:0] input/output signals. A read or write data transaction on HyperBus consists of a series of 16-bit wide, one clock cycle data transfers at the internal HyperRAM core with two corresponding 8-bit wide, one-half-clock-cycle data transfers on the DQ signals. All inputs and outputs are LV-CMOS compatible.

Command, address, and data information is transferred over the 8 HyperBus DQ[7:0] signals. The clock (CK,CK#) is used for information capture by a HyperBus slave device when receiving command, address, or data on the DQ signals. Command or Address values are center aligned with clock transitions.

Every transaction begins with the assertion of CS# and Command-Address (CA) signals, followed by the start of clock transitions to transfer six CA bytes, followed by initial access latency and either read or write data transfers, until CS# is deasserted.

Figure 1.1 Read Transaction, Fixed Latency mode ⁽¹⁾



Note:

1. Initial Latency "Low = 1X Latency Code" is not supported in DDP device.
2. CK# is used in Differential Clock mode, but optional.

The RWDS is a bidirectional signal that indicates:

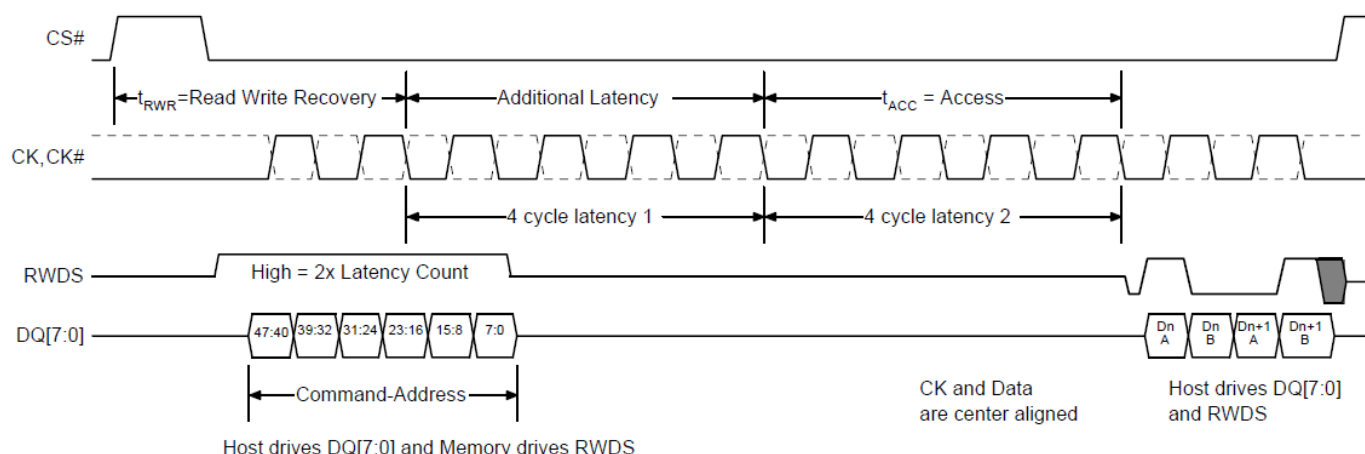
- when data will start to transfer from a HyperRAM device to the master device in read transactions (initial read latency)
- when data is being transferred from a HyperRAM device to the master device during read transactions (as a source synchronous read data strobe)
- when data may start to transfer from a master device to HyperRAM device in write transactions (initial write latency)
- data masking during write data transfers

During the CA transfer portion of a read or write transaction, the device drives RWDS to HIGH because DDP (Dual Die Package) device supports Fixed Latency mode only.

During read data transfers, RWDS is a read data strobe with data values edge aligned with the transitions of RWDS.

During write data transfers, RWDS indicates whether each data byte transfer is masked with RWDS High (invalid and prevented from changing the word location in a memory) or not masked with RWDS Low (valid and written to a memory). Data masking may be used by the host to byte align write data within a memory or to enable merging of multiple non-word aligned writes in a single burst write. During write transactions, data is center aligned with clock transitions.

Figure 1.2 Write Transaction, Fixed Latency mode ⁽¹⁾

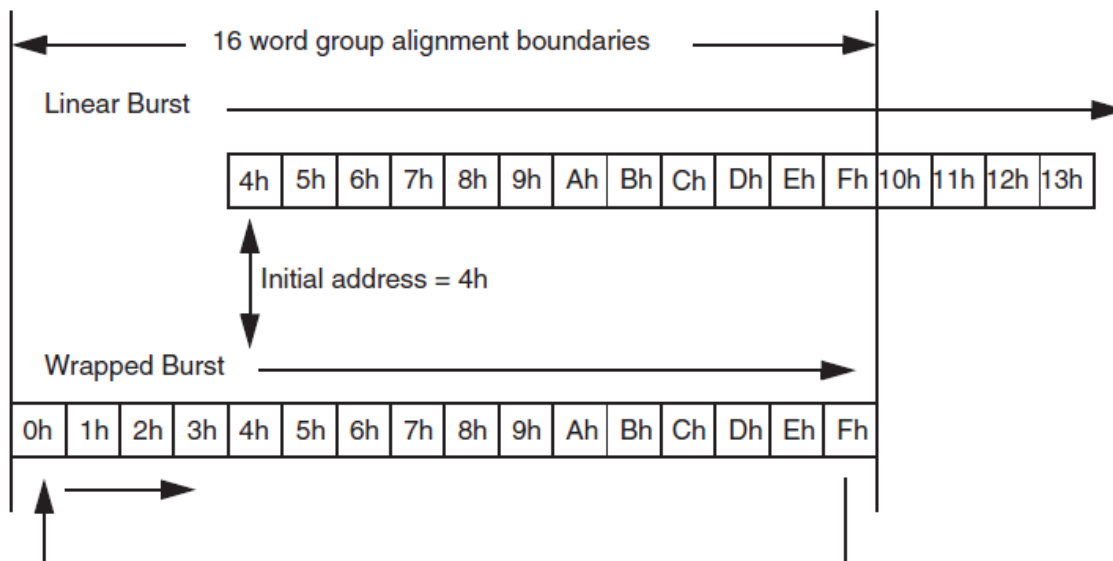


Note:

1. Initial Latency "Low = 1X Latency Code" is not supported in DDP device.
2. CK# is used in Differential Clock mode, but optional.

Read and write transactions are burst oriented, transferring the next sequential word (16-bit) during each clock cycle. Each individual read or write transaction can use either a wrapped or linear burst sequence.

Figure 1.3 Linear Versus Wrapped Burst Sequence



During wrapped burst transactions, accesses start at a selected location and continue to the end of a configured word group aligned boundary, then wrap to the beginning location in the group, then continue back to the starting location. Wrapped bursts are generally used for critical word first cache line fill read transactions.

During linear burst transactions, accesses start at a selected location and continue in a sequential manner until the transaction is terminated when CS# returns High.

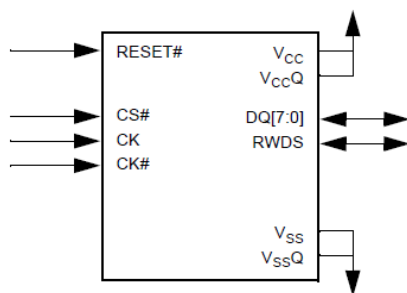
Linear burst transactions are generally used for large contiguous data transfers such as graphic images. Since each transaction command selects the type of burst sequence for that transaction, wrapped and linear bursts transactions can be dynamically intermixed as needed.

Burst transaction can be performed within one die. Burst transaction cannot cross die boundary, so reach to the last address of the die, then continues to the first address of that die.

2. HyperRAM Product Overview

The 1 Gb HyperRAM device is a 1.8V or 3.0V core and I/O, synchronous self-refresh Dynamic RAM (DRAM). The HyperRAM device provides a HyperBus slave interface to the host system. HyperBus has an 8-bit wide DDR data bus and uses only 16-bit word address boundaries. Read data transactions provide 16 bits of data during each clock cycle (8 bits on both clock edges). Write data transactions take 16 bits of data from each clock cycle (8 bits on each clock edge).

Figure 2.1 HyperRAM Interface ⁽¹⁾



Note

1. CK# is used in Differential Clock mode, but optional.

2.1 HyperBus interface

Read and write transactions require two clock cycles to define the target row address and burst type, then an initial access latency of t_{ACC} .

During a read (or write) transaction, after the initial data value has been output (or input), additional data can be read from (or written to) the row on subsequent clock cycles in either a wrapped or linear sequence. When configured in Linear Burst mode, the device will automatically fetch the next sequential row from the memory array to support a continuous linear burst. Simultaneously accessing the next row in the array while the read or write data transfer is in progress, allows for a linear sequential burst operation that can provide a sustained data rate of 500 MB/s for 1.8V device.
 $(1 \text{ byte of 8-bit data bus}) * 2 (\text{data clock edges}) * 250 \text{ MHz} = 500 \text{ MB/s}$.

3. HyperRAM Signal Descriptions

3.1 Input/Output Summary

HyperRAM signals are shown in [Table 3.1](#). Active Low signal names have a hash symbol (#) suffix.

Table 3.1 I/O Summary

Symbol	Type	Description
CS#	Input	Chip Select. Bus transactions are initiated with a HIGH to LOW transition. Bus transactions are terminated with a LOW to HIGH transition. The master device has a separate CS# for each slave.
CK, CK# ⁽¹⁾	Input	Differential Clock. Command, address, and data information is output with respect to the crossing of the CK and CK# signals. Use of differential clock is optional. Single Ended Clock. CK# is not used, only a single ended CK is used. The clock is not required to be free-running.
DQ[7:0]	Input/Output	Data Input/Output. Command, Address and Data information is transferred on these signals during Read and Write transactions.
RWDS	Input/Output	Read-Write Data Strobe. During the command/address portion of all bus transactions, RWDS is always HIGH in a DDP device. Slave output during read data transfer, data is edge-aligned with RWDS. Slave input during data transfer in write transactions to function as a data mask.
RESET#	Input, Internal Pull-up	Hardware RESET. When LOW, the slave device will self initialize and return to the STANDBY state. RWDS and DQ[7:0] are placed into the HIGH-Z state when RESET# is LOW. The slave RESET# input includes a weak pull-up, if RESET# is left unconnected it will be pulled up to the HIGH state.
V _{CC}	Power Supply	Array Power.
V _{CCQ}	Power Supply	Input/Output Power.
V _{SS}	Power Supply	Array Ground.
V _{SSQ}	Power Supply	Input/Output Ground.
RFU	No Connect	Reserved for Future Use. May or may not be connected internally, the signal/ball location should be left unconnected and unused by PCB routing channel for future compatibility. The signal/ball may be used by a signal in the future.

Note

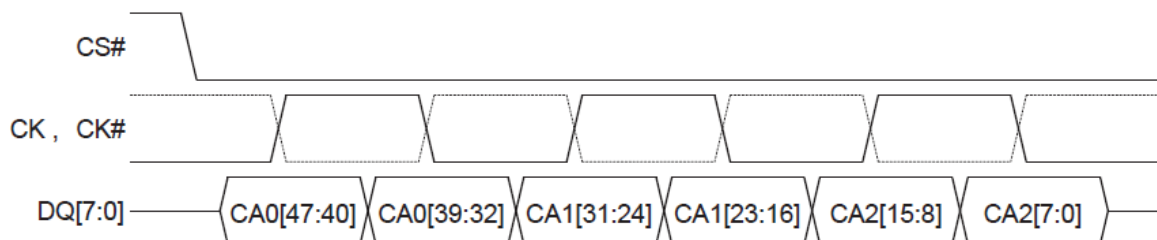
1. CK# is used in Differential Clock mode, but optional connection. Tie the CK# input pin to either VccQ or VssQ if not connected to the host controller, but do not leave it floating.

3.2 Command/Address Bit Assignments

All HyperRAM bus transactions can be classified as either read or write. A bus transaction is started with CS# going Low with clock in idle state (CK=Low and CK#=High). The first three clock cycles transfer three words of Command/Address (CA0, CA1, CA2) information to define the transaction characteristics. The Command/Address words are presented with DDR timing, using the first six clock edges. The following characteristics are defined by the Command/Address information:

- Read or Write transaction
- Address Space: memory array space or register space
- Register space is used to access Device Identification (ID) registers and Configuration Registers (CR) that identify the device characteristics and determine the slave specific behavior of read and write transfers on the HyperBus interface.
- Whether a transaction will use a linear or wrapped burst sequence.
- The target row (and half-page) address (upper order address).
- The target column (word within half-page) address (lower order address).

Figure 3.1 Command-Address Sequence



Notes:

1. Figure 3.1 shows the initial three clock cycles of all transactions on the HyperBus.
2. CK# of differential clock is shown as dashed line waveform.
3. Command-Address information is "center aligned" with the clock during both Read and Write transactions.
4. Data bits in each byte are always in high to low order with bit 7 on DQ7 and bit 0 on DQ0.

Table 3.2 Command-Address Bit Assignment to DQ Signals

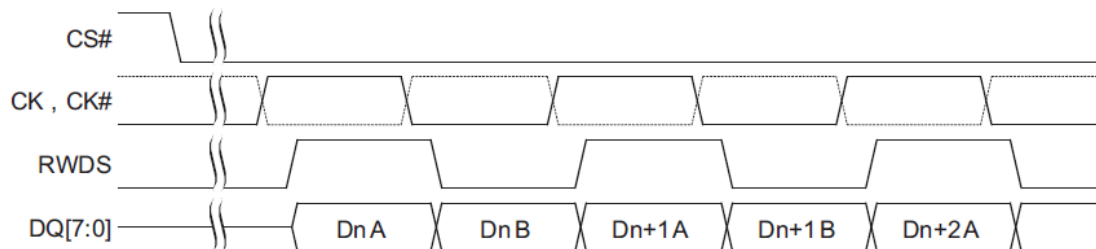
Signal	CA0[47:40]	CA0[39:32]	CA1[31:24]	CA1[23:16]	CA2[15:8]	CA2[7:0]
DQ[7]	CA[47]	CA[39]	CA[31]	CA[23]	CA[15]	CA[7]
DQ[6]	CA[46]	CA[38]	CA[30]	CA[22]	CA[14]	CA[6]
DQ[5]	CA[45]	CA[37]	CA[29]	CA[21]	CA[13]	CA[5]
DQ[4]	CA[44]	CA[36]	CA[28]	CA[20]	CA[12]	CA[4]
DQ[3]	CA[43]	CA[35]	CA[27]	CA[19]	CA[11]	CA[3]
DQ[2]	CA[42]	CA[34]	CA[26]	CA[18]	CA[10]	CA[2]
DQ[1]	CA[41]	CA[33]	CA[25]	CA[17]	CA[9]	CA[1]
DQ[0]	CA[40]	CA[32]	CA[24]	CA[16]	CA[8]	CA[0]

Table 3.3 Command/Address Bit Assignments

CA Bit#	Bit Name	Bit Function
47	R/W#	Identifies the transaction as a read or write. R/W#=1 indicates a Read transaction R/W#=0 indicates a Write transaction
46	Address Space (AS)	Indicates whether the read or write transaction accesses the memory or register space. AS=0 indicates memory space AS=1 indicates the register space The register space is used to access device ID and Configuration registers.
45	Burst Type	Indicates whether the burst will be linear or wrapped. Burst Type=0 indicates wrapped burst Burst Type=1 indicates linear burst
44-16	Row & Upper Column Address	Row & Upper Column component of the target address: System word address bits A31-A3 Any upper Row address bits not used by a particular device density should be set to 0 by the host controller master interface. The size of Rows and therefore the address bit boundary between Row and Column address is slave device dependent.
15-3	Reserved	Reserved for future column address expansion. Reserved bits are don't care in current HyperBus devices but should be set to 0 by the host controller master interface for future compatibility.
2-0	Lower Column Address	Lower Column component of the target address: System word address bits A2-0 selecting the starting word within a half-page.

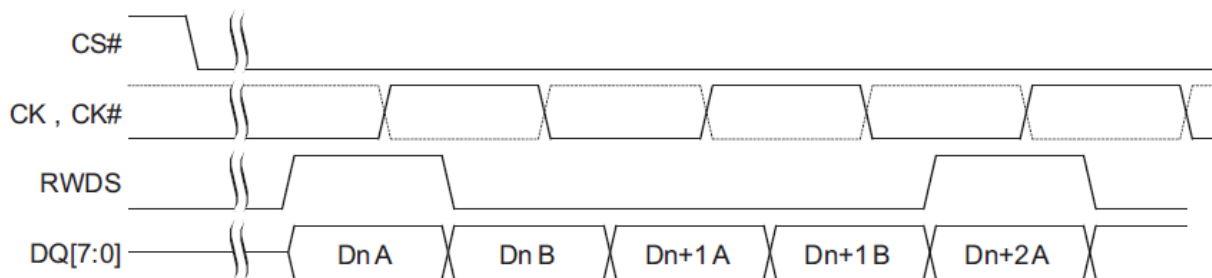
Notes:

1. A Row is a group of words relevant to the internal memory array structure. The number of Rows may be used in the calculation of a distributed refresh interval for HyperRAM memory.
2. The Column address selects the burst transaction starting word location within a Row. The Column address is split into an upper and lower portion. The upper portion selects an 8-word (16-byte) Half-page and the lower portion selects word within a Half-page where a read or write transaction burst starts.
3. The initial read access time starts when the Row and Upper Column (Half-page) address bits are captured by a slave interface. Continuous linear read burst is enabled by memory devices internally interleaving access to 16 byte half-pages.
4. HyperBus protocol address space limit, assuming: 29 Row & Upper Column address bits
3 Lower Column address bits
Each address selects a word (16-bit) wide data value

Figure 3.2 Data Placement During a Read Transaction

Notes:

1. Figure 3.2 shows a portion of a Read transaction on the HyperBus. CK# of differential clock is shown as dashed line waveform.
2. Data is "edge aligned" with the RWDS serving as a read data strobe during read transactions.
3. Data is always transferred in full word increments (word granularity transfers).
4. Word address increments in each clock cycle. Byte A is between RWDS rising and falling edges and is followed by Byte B between RWDS falling and rising edges, of each word.
5. Data bits in each byte are always in HIGH to LOW order with bit 7 on DQ7 and bit 0 on DQ0.

Figure 3.3 Data Placement During a Write Transaction



Notes:

1. Figure shows a portion of a Write transaction on the HyperBus.
2. Data is "center aligned" with the clock during a Write transaction.
3. RWDS functions as a data mask during write data transfers with initial latency.
4. RWDS is not driven by the master during write data transfers with zero initial latency. Full data words are always written in this case. RWDS may be driven LOW or left High-Z by the slave in this case.

3.3 Read Transactions (Memory array and registers)

The HyperBus master begins a transaction by driving CS# LOW while clock is idle. Then the clock begins toggling while CA words are transferred.

In CA0, CA[47] = 1 indicates that a Read transaction is to be performed. CA[46] = 0 indicates the memory space is being read or CA[46] = 1 indicates the register space is being read. CA[45] indicates the burst type (wrapped or linear). Read transactions can begin the internal array access as soon as the row and upper column address has been presented in CA0 and CA1 (CA[47:16]). CA2 (CA[15:0]) identifies the target Word address within the chosen row.

The HyperBus master then continues clocking for a number of cycles defined by the latency count setting in configuration register 0. The initial latency count required for a particular clock frequency is based on RWDS. **RWDS is always HIGH during the CA cycles in DDP device**, an additional latency count is inserted. Once these latency clocks have been completed the memory starts to simultaneously transition the Read-Write Data Strobe (RWDS) and output the target data.

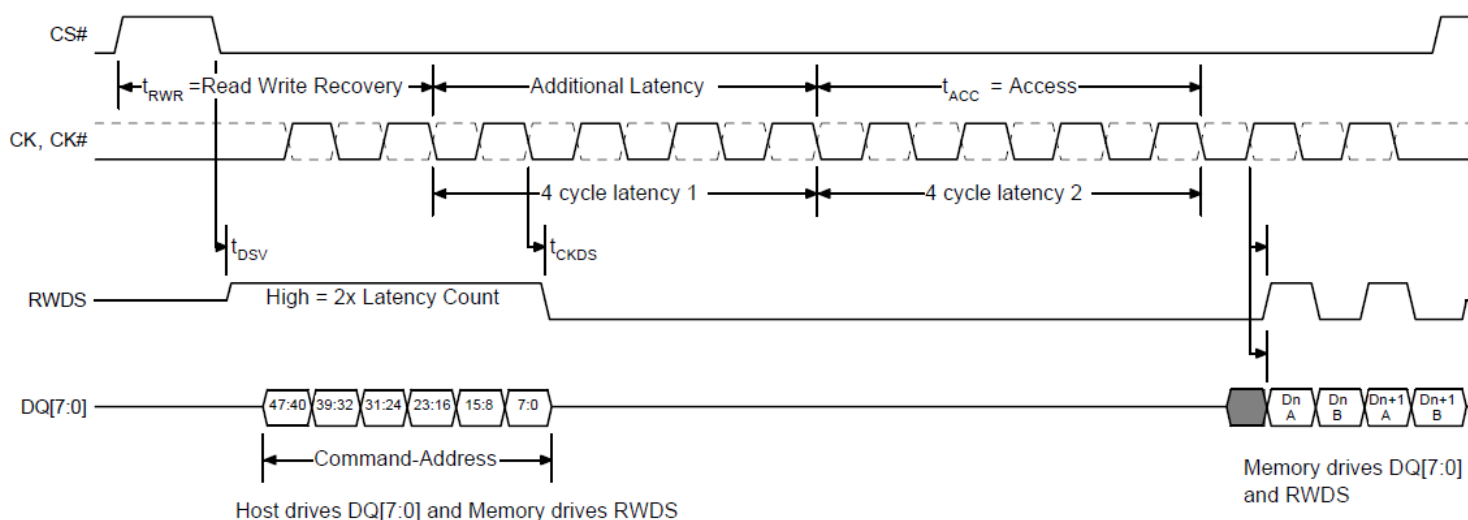
New data is output edge aligned with every transition of RWDS. Data will continue to be output as long as the host continues to transition the clock while CS# is LOW. Note that burst transactions should not be so long as to prevent the memory from doing distributed refreshes.

Wrapped bursts will continue to wrap within the burst length and linear burst will output data in a sequential manner across row boundaries. When a linear burst read reaches the last address of a die, continuing the burst beyond the last address of the die will provide data from the first address of the die. **Burst operations cannot cross the die boundary.**

Read transfers can be ended at any time by bringing CS# HIGH when the clock is idle.

The clock is not required to be free-running. The clock may remain idle while CS# is HIGH.

Figure 3.4 Read Transaction with Fixed Latency mode.



Notes:

1. Transactions are initiated with CS# falling while CK=LOW and CK#=HIGH.
2. CS# must return HIGH before a new transaction is initiated.
3. CK# is the complement of the CK signal. CK# of a differential clock is shown as a dashed line waveform.
4. Read access array starts once CA[23:16] is captured.
5. During CA, RWDS is driven by the memory and is always HIGH in a DDP device.
6. In this read transaction example, the initial latency count was set to four clocks.
7. In this read transaction a RWDS HIGH indication during CA period delays output of target data by an additional four clocks.
8. The memory device drives RWDS during read transactions.

3.4 WRITE TRANSACTIONS (MEMORY ARRAY WRITE)

The HyperBus master begins a transaction by driving CS# LOW while clock is idle. Then the clock begins toggling while Command-Address CA words are transferred.

In CA0, CA[47] = 0 indicates that a Write transaction is to be performed. CA[46] = 0 indicates the memory space is being written. CA[45] indicates the burst type (wrapped or linear). Write transactions can begin the internal array access as soon as the row and upper column address has been presented in CA0 and CA1 (CA[47:16]). CA2 (CA[15:0]) identifies the target word address within the chosen row.

The HyperBus master then continues clocking for a number of cycles defined by the latency count setting in configuration register 0. The initial latency count required for a particular clock frequency is based on RWDS.

RWDS is always HIGH during the CA cycles in DDP device, an additional latency count is inserted.

Once these latency clocks have been completed the HyperBus extended-IO master starts to output the target data. Write data is center aligned with the clock edges. The first 8-bit data is captured by the memory on the rising edge of CK and the second 8-bit data is captured on the falling edge of CK.

During the CA clock cycles, RWDS is driven by the memory.

During the write data transfers, RWDS is driven by the host master interface as a data mask. When data is being written and RWDS is HIGH the 8-bit data will be masked and the array will not be altered. When data is being written and RWDS is LOW the data will be placed into the array. Because the master is driving RWDS during write data transfers, neither the master nor the HyperRAM device are able to indicate a need for latency within the data transfer portion of a write transaction. The acceptable write data burst length setting is also shown in configuration register 0.

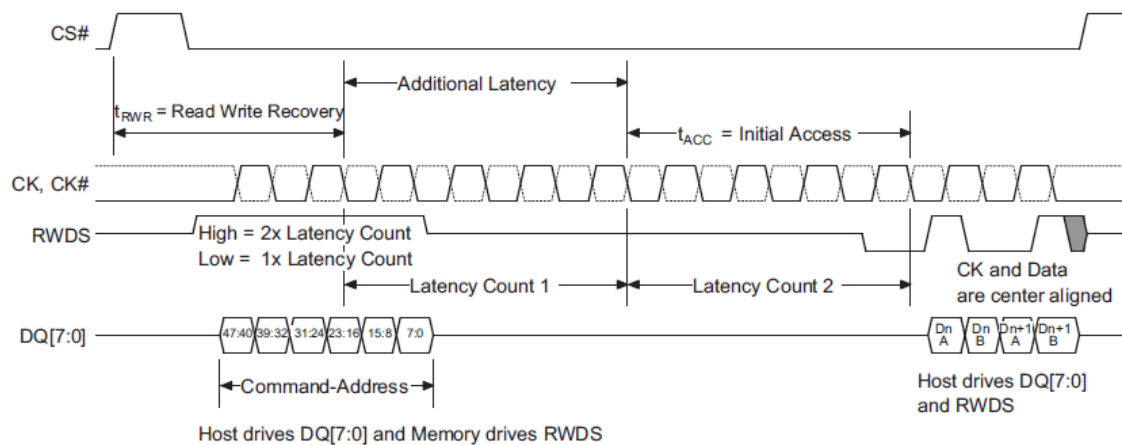
Data will continue to be transferred as long as the HyperBus master continues to transition the clock while CS# is LOW. Note that burst transactions should not be so long as to prevent the memory from distributed refreshes. Legacy format wrapped bursts will continue to wrap within the burst length. Hybrid wrap will wrap once then switch to linear burst starting at the next wrap boundary. Linear burst accepts data in a sequential manner across page boundaries. Write transfers can be ended at any time by bringing CS# High when the clock is idle.

When a linear burst write reaches the last address of a die, continuing the burst will write to the beginning address of that die.

Burst operations cannot cross the die boundary.

The clock is not required to be free-running. The clock may remain idle while CS# is HIGH.

Figure 3.5 Write Transaction with Fixed Latency mode



Notes:

1. Transactions must be initiated with CK=LOW and CK#=HIGH.
2. CS# must return HIGH before a new transaction is initiated.
3. During CA, RWDS is driven by the memory and is always HIGH in a DDP device.
4. In this example, RWDS indicates that additional initial latency cycles are required.

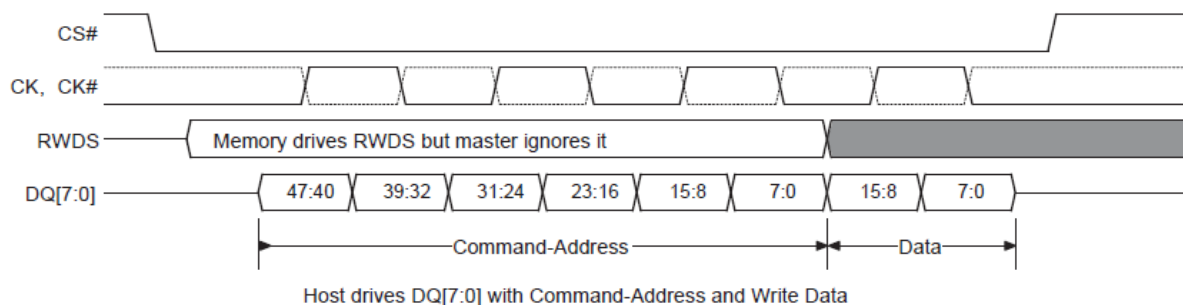
3.5 Write Transactions without Initial Latency (Register Write)

Write transaction starts with the first three clock cycles providing the Command/Address information indicating the transaction characteristics. CA0 may indicate that a Write transaction is to be performed and also indicates the address space and burst type (wrapped or linear).

Writes without initial latency are used for register space writes. HyperRAM device write transactions with zero latency mean that the CA cycles are followed by write data transfers. Writes with zero initial latency, do not have a turn around period for RWDS. The HyperRAM device will always drive RWDS during the Command-Address period to indicate whether extended latency is required for a transaction that has initial latency. However, the RWDS is driven before the HyperRAM device has received the first byte of CA i.e. before the HyperRAM device knows whether the transaction is a read or write to register space. In the case of a write with zero latency, the RWDS state during the CA period does not affect the initial latency of zero. Since master write data immediately follows the Command-Address period in this case, the HyperRAM device may continue to drive RWDS HIGH or may take RWDS to High-Z during write data transfer. The master must not drive RWDS during Writes with zero latency. Writes with zero latency do not use RWDS as a data mask function.

The first 8-bit data is presented on the rising edge of CK and the second 8-bit data is presented on the falling edge of CK. Write data is center aligned with the clock inputs. Write transfers can be ended at any time by bringing CS# HIGH when clock is idle. The clock is not required to be free-running.

Figure 3.6 Register Write Operation without Initial Latency



Note:

1. Latency is not applicable during the Register Write. The RWDS driven HIGH after the CS# LOW should be ignored by the host. The register write data byte immediately follows the last CA byte (zero clock latency)

4. Memory Space

When CA[46] is 0 a read or write transaction accesses the DRAM memory array.

Table 4.1 Memory Space Address Map (word based – 16 bits)

Unit Type	Count	System Word Address Bits	CA Bits	Notes
Rows within 1Gb device	131,072 (rows)	A25-A9	38-22	-
Rows within 512Mb device	65,536 (rows)	A24-A9	37-22	-
Row	64* Half pages	A8-A3	21-16	Each row has 64 Half-pages. Each Half-page has eight 16-bit words. Therefore, each row has 512 words (16-bit) or 1KB.
Half-page	8 * 16-bit words	A2-A0	2-0	Half-page (HP) address is also referenced as upper column address. A word within a Half-page address is also referred to as lower column address.

5. Register Space

5.1 HYPERBUS interface

When CA[46] is 1 a read or write transaction accesses the Register Space.

Table 5.1 Register Space Address Map

Register	System Address	—	—	—	31-27	21-19	18-11	10-3	—	2-0
	CA Bits	47	46	45 ⁽¹⁾	44-40	39-32	31-24	23-16	15-8	7-0
Identification register 0 Read ⁽²⁾		C0h or E0h				00h	00h	000h	00h	00h
Identification register 1 Read ⁽²⁾		C0h or E0h				00h	00h	000h	00h	01h
Configuration register 0 Read		C0h or E0h				00h	01h	000h	00h	00h
Configuration register 0 Write		60h				00h	01h	000h	00h	00h
Configuration register 1 Read		C0h or E0h				00h	01h	000h	00h	01h
Configuration register 1 Write		60h				00h	01h	000h	00h	01h

Notes:

1. CA45 may be either 0 or 1 for either wrapped or linear read. CA45 must be 1 as only linear single word register writes are supported.
2. The burst type (wrapped/linear) definition is not supported in register reads. Hence C0h/E0h have the same effect.

5.2 Register Space Access

Register default values are loaded upon power-up or hardware reset. The registers can be altered at any time while the device is in the standby state.

Loading a register is accomplished with write transaction without initial latency using a single 16-bit word write transaction.

Each register is written with a separate single word write transaction. Register write transactions have zero latency, the single word of data immediately follows the CA. RWDS is not driven by the host during the write because RWDS is always driven by the memory during the CA cycles to indicate whether a memory array refresh is in progress. Because a register space write goes directly to a register, rather than the memory array, there is no initial write latency, related to an array refresh that may be in progress. In a register write, RWDS is also not used as a data mask because both bytes of a register are always written and never masked.

Register write is written in both die at the same time for DDP device.

Reserved register fields must be written with their default value. Writing reserved fields with other than default values may produce undefined results.

Notes

- The host must not drive RWDS during a write to register space.
- The RWDS signal is driven by the memory during the Command-Address period based on whether the memory array is being refreshed. This refresh indication does not affect the writing of register data.
- The RWDS signal returns to high impedance after the Command-Address period. Register data is never masked. Both data bytes of the register data are loaded into the selected register.

Reading of a register is accomplished with read transaction with a double initial latency using a single 16 bit read transaction. If more than one word is read, the same register value is repeated in each word. The contents of the register are returned in the same manner as reading the memory array data with two latency counts in a DDP device. The latency count is defined in the Configuration Register 0 Read Latency field (CR0[7:4]).

5.3 Device Identification Registers

There are two read only, non-volatile, word registers, that provide information on the device selected when CS# is LOW. The device information fields identify:

- Manufacturer
- Type
- Density
 - Row address bit count
 - Column address bit count

Table 5.2 ID Register 0 Bit Assignments

Bits	Function	Settings (Binary)
15-14	Reserved	00 - default
13	Reserved	0 - default
12-8	Row Address Bit Count	10000b - Seventeen Row address bits (1Gb)
7-4	Column Address Bit Count	1000b - Nine column address bits
3-0	Manufacturer	0000 – Reserved 0011 - ISSI 0010 to 1111 - Reserved

Table 5.3 ID Register 1 Bit Assignments

Bits	Function	Settings (Binary)
15-4	Reserved	0000_0000_0000b (default)
3-0	Device Type	0001 – HyperRAM 2.0

5.3.1 Density and Row Boundaries

The DRAM array size (density) of the device can be determined from the total number of system address bits used for the row and column addresses as indicated by the Row Address Bit Count and Column Address Bit Count fields in the ID0 register. For example: a 1Gbit HyperRAM device has 9 column address bits and 17 row address bits for a total of 26 word address bits = $2^{26} = 64M \times 16\text{-bit}$ or 1Gb. The 9 column address bits indicate that each row holds $2^9 \times 16\text{-bit}$ or 8192 bits. The row address bit count indicates there are 131,072 rows to be refreshed within each array refresh interval. The row count is used in calculating the refresh interval.

5.4 Configuration Register 0

Configuration Register 0 (CR0) is used to define the power state and access protocol operating conditions for the HyperRAM device. Configurable characteristics include:

- Wrapped Burst Length (16, 32, 64, or 128 byte aligned and length data group)
- Wrapped Burst Type
 - Legacy wrap (Sequential access with wrap around within a selected length and aligned group).
 - Hybrid wrap (Legacy wrap once then linear burst at start of the next sequential group).
- Initial Latency
- Fixed Latency
 - 1Gb device is a DDP of two 512Mb, and supports Fixed Latency only.
- Output Drive Strength
- Deep Power Down (DPD) mode

Table 5.4 Configuration Register Bit Assignments

CR0 Bit	Function	Settings (Binary)
[15]	Deep Power Down Enable	1 – Normal operation (default). HYPERRAM will automatically set the value to “1” after DPD exit. 0 – Writing 0 causes the device to enter Deep Power Down.
[14:12]	Drive Strength	000- 34 ohms (default) 001- 115 ohms 010- 67 ohms 011- 46 ohms 100- 34 ohms 101- 27 ohms 110- 22 ohms 111- 19 ohms
[11:8]	Reserved	1 - Reserved (default) Reserved for Future Use. When writing this register, these bits should be set to 1 for future compatibility.
[7:4]	Initial Latency	0000 - 5 Clock Latency @ 133MHz Max Frequency 0001 - 6 Clock Latency @ 166MHz Max Frequency 0010 - 7 Clock Latency @ 250MHz-1.8V, 200MHz-3.0V Max Frequency (default) 0011 - 8 Clock Latency @ 250MHz-1.8V, 200MHz-3.0V Max Frequency 0100 – Reserved ... 1101 - Reserved 1110 - 3 Clock Latency@ 85MHz Max Frequency 1111 - 4 Clock Latency @ 104MHz Max Frequency
[3]	Fixed Latency Enable	1 - Fixed 2 times Initial Latency (default) Note: CR0[3] of each die of DDP device must be programmed as “1” (Fixed Latency mode)
[2]	Hybrid Burst Enable	0 - Wrapped burst sequence to follow hybrid burst sequencing 1 - Wrapped burst sequence in legacy wrapped burst manner (default) This bit setting is effective only when the “Burst Type” bit in the Command/Address register is set to ‘0’. CA[45] = 0; otherwise, it is ignored.
[1:0]	Burst Length	00 - 128 bytes 01 - 64 bytes 10 - 16 bytes 11 - 32 bytes (default)

5.4.1 Wrapped Burst

A wrapped burst transaction accesses memory within a group of words aligned on a word boundary matching the length of the configured group. Wrapped access groups can be configured as 16, 32, 64, or 128 8-bit data alignment and length. During wrapped transactions, access starts at the Command-Address selected location within the group, continues to the end of the configured word group aligned boundary, then wraps around to the beginning location in the group, then continues back to the starting location.

Wrapped bursts are generally used for critical 8-bit first instruction or data cache line fill read accesses.

5.4.2 Hybrid Burst

The beginning of a hybrid burst will wrap within the target address wrapped burst group length before continuing to the next half-page of data beyond the end of the wrapped group. Continued access is in linear burst order until the transfer is ended by returning CS# HIGH. This hybrid of a wrapped burst followed by a linear burst starting at the beginning of the next burst group, allows multiple sequential address cache lines to be filled in a single access. The first cache line is filled starting at the critical word. Then the next sequential line in memory can be read in to the cache while the first line is being processed.

Table 5.5 CR0[2] Control of Wrapped Burst Sequence

Bit	Default Value	Name
2	1	Hybrid Burst Enable CR[2]= 0: Wrapped burst sequences to follow hybrid burst sequencing CR[2]= 1: Wrapped burst sequences in legacy wrapped burst manner

Table 5.6 Example Wrapped Burst Sequences

Burst Selection		Burst Type	Wrap Boundary (8-bit)	Start Address (Hex)	Address Sequence (Hex) (16-bit data)
CA[4:5]	CR0[2:0]				
0	000	Hybrid 128	128 Wrap once then Linear	XXXXXX03	03, 04, 05, 06, 07, 08, 09, 0A, 0B, 0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 1A, 1B, 1C, 1D, 1E, 1F, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 2A, 2B, 2C, 2D, 2E, 2F, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 3A, 3B, 3C, 3D, 3E, 3F, 00, 01, 02 (wrap complete, now linear beyond the end of the initial 128 byte wrap group) 40, 41, 42, 43, 44, 45, 46, 47, 48, 49, 4A, 4B, 4C, 4D, 4E, 4F, 50, 51, ...
0	001	Hybrid 64	64 Wrap once then Linear	XXXXXX03	03, 04, 05, 06, 07, 08, 09, 0A, 0B, 0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 1A, 1B, 1C, 1D, 1E, 1F, 00, 01, 02, (wrap complete, now linear beyond the end of the initial 64 byte wrap group) 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 2A, 2B, 2C, 2D, 2E, 2F, 30, 31, ...
				XXXXXX2E	2E, 2F, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 3A, 3B, 3C, 3D, 3E, 3F, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 2A, 2B, 2C, 2D, (wrap complete, now linear beyond the end of the initial 64 byte wrap group) 40, 41, 42, 43, 44, 45, 46, 47, 48, 49, 4A, 4B, 4C, 4D, 4E, 4F, 50, 51, ...
0	010	Hybrid 16	16 Wrap once then Linear	XXXXXX02	02, 03, 04, 05, 06, 07, 00, 01, (wrap complete, now linear beyond the end of the initial 16 byte wrap group) 08, 09, 0A, 0B, 0C, 0D, 0E, 0F, 10, 11, 12, ...
				XXXXXX0C	0C, 0D, 0E, 0F, 08, 09, 0A, 0B, (wrap complete, now linear beyond the end of the initial 16 byte wrap group) 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 1A, ...
0	011	Hybrid 32	32 Wrap once then Linear	XXXXXX0A	0A, 0B, 0C, 0D, 0E, 0F, 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, ... (wrap complete, now linear beyond the end of the initial 32 byte wrap group)
0	100	Wrap 128	128	XXXXXX03	03, 04, 05, 06, 07, 08, 09, 0A, 0B, 0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 1A, 1B, 1C, 1D, 1E, 1F, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 2A, 2B, 2C, 2D, 2E, 2F, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 3A, 3B, 3C, 3D, 3E, 3F, 00, 01, 02, ...
0	101	Wrap 64	64	XXXXXX03	03, 04, 05, 06, 07, 08, 09, 0A, 0B, 0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 1A, 1B, 1C, 1D, 1E, 1F, 00, 01, 02, ...
				XXXXXX2E	2E, 2F, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 3A, 3B, 3C, 3D, 3E, 3F, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 2A, 2B, 2C, 2D, ...
0	110	Wrap 16	16	XXXXXX02	02, 03, 04, 05, 06, 07, 00, 01, ...
				XXXXXX0C	0C, 0D, 0E, 0F, 08, 09, 0A, 0B, ...
0	111	Wrap 32	32	XXXXXX0A	0A, 0B, 0C, 0D, 0E, 0F, 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, ...
				XXXXXX1E	1E, 1F, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 1A, 1B, 1C, 1D, ...
1	XXX	Linear	Linear Burst	XXXXXX03	03, 04, 05, 06, 07, 08, 09, 0A, 0B, 0C, 0D, 0E, 0F, 10, 11, 12, 13, 14, 15, 16, 17, 18, ...

5.4.3 Initial Latency

Memory Space read and write transactions or Register Space read transactions require some initial latency to open the row selected by the Command-Address. This initial latency is t_{ACC} . The number of latency clocks needed to satisfy t_{ACC} depends on the HyperBus frequency and can vary from 3 to 8 clocks. The value in CR0[7:4] selects the number of clocks for initial latency. **The default value is 7 clocks, allowing for operation up to a maximum frequency of 250MHz (1.8V)/200MHz(3.0V)** prior to the host system setting a lower initial latency value that may be more optimal for the system.

In the event a distributed refresh is required at the time a Memory Space read or write transaction or Register Space read transaction begins, the RWDS signal goes HIGH during the Command-Address to indicate that an additional initial latency is being inserted to allow a refresh operation to complete before opening the selected row.

Register Space write transactions always have zero initial latency. The level of RWDS during the Command-Address period does not affect the placement of register data immediately after the Command-Address, as there is no initial latency needed to capture the register data. A refresh operation may be performed in the memory array in parallel with the capture of register data.

5.4.4 Fixed Latency

A configuration register option bit CR0[3] must be programmed as '1' in a DDP device for fixed initial latency, which is provided to make all Memory Space read and write transactions or Register Space read transactions require the same initial latency by always driving RWDS HIGH during the Command-Address to indicate that two initial latency periods are required. This fixed initial latency is independent of any need for a distributed refresh, it simply provides a fixed (deterministic) initial latency for all of these transaction types. The fixed latency option may simplify the design of some HyperBus memory controllers or ensure deterministic transaction performance. Fixed latency is the default POR or reset configuration. The system may clear this configuration bit to disable fixed latency and allow variable initial latency with RWDS driven HIGH only when additional latency for a refresh is required.

5.4.5 Driver Strength

DQ and RWDS signal line loading, length, and impedance vary depending on each system design. Configuration register bits CR0[14:12] provide a means to adjust the DQ[7:0] and RWDS signal output impedance to customize the DQ and RWDS signal impedance to the system conditions to minimize high speed signal behaviors such as overshoot, undershoot, and ringing. The default POR or reset configuration value is 000b to select the mid point of the available output impedance options.

The impedance values shown are typical for both pull-up and pull-down drivers at typical silicon process conditions, nominal operating voltage (1.8V or 3V) and 50°C. The impedance values may vary from the typical values depending on the Process, Voltage, and Temperature (PVT) conditions. Impedance will increase with slower process, lower voltage, or higher temperature. Impedance will decrease with faster process, higher voltage, or lower temperature.

Each system design should evaluate the data signal integrity across the operating voltage and temperature ranges to select the best drive strength settings for the operating conditions.

5.4.6 Deep Power Down

When the HYPERRAM device is not needed for system operation, it may be placed in a very low power consuming state called deep power down (DPD), by writing '0' to CR0[15].

When CR0 [15] is cleared to '0', the device enters the DPD state within tDPDIN time and all refresh operations stop. The data in the device is lost, (becomes invalid without refresh) during DPD state.

Exiting DPD requires driving CS# LOW then HIGH, POR, or a reset. Only CS# and RESET# signals are monitored during DPD mode.

5.5 Configuration Register 1

Configuration Register 1 (CR1) is used to define the refresh array size, refresh rate and hybrid sleep for the HYPERRAM device. Configurable characteristics include:

- Master clock type
- Hybrid sleep state
- Partial array refresh
- Refresh rate

Table 5.7 Configuration Register Bit Assignments

CR1 Bit	Function	Setting (Binary)
[15:7]	Reserved	11111111 - Reserved (default) When writing this register, these bits should keep 11111111 for future compatibility.
[6]	Master clock type	1 – Single-ended - CK (default) 0 – Differential - CK, CK#
[5]	Hybrid Sleep	1 – Causes the device to enter hybrid sleep mode 0 – Normal operation (default)
[4:2]	Partial array refresh	000 – Full array (default) 001 – Bottom 1/2 array 010 – Bottom 1/4 array 011 – Bottom 1/8 array 100 – None 101 – Top 1/2 array 110 – Top 1/4 array 111 – Top 1/8 array
[1:0]	Distributed Refresh Interval (Read Only)	10 – 1 μ s tCSM for Automotive Grade (A2) 11 – Reserved 00 – Reserved 01 – 4 μ s tCSM for Industrial Grade (I)

5.5.1 Master clock type

Two clock type, namely single ended and differential, are supported. CR1[6] selects which type to use.

- In the single ended clock mode (by default), CK# input is not enabled; hence it may be left either floating or biased to HIGH or LOW.
- In the differential clock mode (when enabled), the CK# input can't be left floating. It must be either driven by the host, or biased to HIGH or LOW.

5.5.2 Partial array refresh

The partial array refresh configuration restricts the refresh operation in HyperRAM to a portion of the memory array specified by CR1[4:2]. This reduces the standby current. The default configuration refreshes the whole array.

For this DDP device, the area under partial refresh will be allocated into partial area of each stacked die.

Bit	Function	Settings (Binary)	Active Area of Die 1	Active Area of Die 0
CR[11:9]	Partial Array Refresh	000b – Full Array of 1Gb	Full Array of Die 1	Full Array of Die 0
		001b - Bottom 1/2 Array of 1Gb	None	Full Array of Die 0
		000b - Bottom 1/4 Array of 1Gb	None	Bottom 1/2 Array of Die
		001b - Bottom 1/8 Array of 1Gb	None	Bottom 1/4 Array of Die
		100b - Reserved	None	None
		101b - Top 1/2 Array of 1Gb	Full Array of Die 1	None
		110b - Top 1/4 Array of 1Gb	Top 1/2 Array of Die 1	None
		111b - Top 1/8 Array of 1Gb	Top 1/4 Array of Die 1	None

5.5.3 Hybrid sleep (HS)

When the HYPERRAM is not needed for system operation but data in the device needs to be retained, it may be placed in hybrid sleep state to save more power. Enter hybrid sleep state by writing 1 to CR1[5]. Bringing CS# LOW will cause the device to exit HS state and reset CR1[5] to '0'. Also, POR or a hardware reset will cause the device to exit hybrid state. Note that POR or a hardware reset disables refresh where the memory core data can potentially get lost.

5.5.4 Distributed Refresh Interval

The HYPERRAM device is built with volatile DRAM array requires periodic refresh of all bits in it. The refresh operation can be done by an internal self-refresh logic that will evenly refresh the memory array automatically.

The automatic refresh operation can only be done when the memory array is not actively read or written by the host system. The refresh logic waits for the end of any active read or write before doing a refresh, if a refresh is needed at that time. If a new read or write begins before the refresh is completed, the memory will drive RWDS HIGH during the CA period to indicate that an additional initial latency time is required at the start of the new access in order to allow the refresh operation to complete before starting the new access. The evenly distributed refresh operations require a maximum refresh interval between two adjacent refresh operations. The maximum distributed refresh interval varies with temperature.

Table 5.8 Array refresh interval per temperature

Device Temperature (°C)	CR1 Setting [1:0]	Refresh Interval t_{CSM}
I Grade (-40°C ~ +85°C)	01b	4 us
Auto A2 Grade (-40°C ~ +105°C)	10b	1 us

The distributed refresh operation requires that the host does not do burst transactions longer than the distributed refreshes interval to prevent the memory from unable doing the distributed refresh operation when it is needed. This sets an upper limit on the length of read and write transactions so that the automatic distributed refresh can be done between transactions.

This limit is called the CS# LOW maximum time (t_{CSM}) and the t_{CSM} will be equal to the maximum distributed refresh interval. The host system is required to respect the t_{CSM} value by terminating each transaction before violating t_{CSM} . This can be done by host memory controller splitting long transactions when reaching the t_{CSM} limit, or by host system hardware or software not performing a single burst read or write transactions that would be longer than t_{CSM} .

The maximum refresh interval is longer at lower temperatures such that t_{CSM} could be increased to allow longer transactions. The host may determine the operating temperature from a temperature sensor in the system and use t_{CSM} value from the table accordingly, or it may determine dynamically by reading the read only CR1[1:0] bits in order to set the distributed refresh interval prior to the HYPERRAM access.

6. Interface States

6.1 Power Conservative Modes

6.1.1 Interface Standby

Standby is the default, low power, state for the interface while the device is not selected by the host for data transfer (CS# = High). All inputs, and outputs other than CS# and RESET# are ignored in this state.

6.1.2 Active Clock Stop

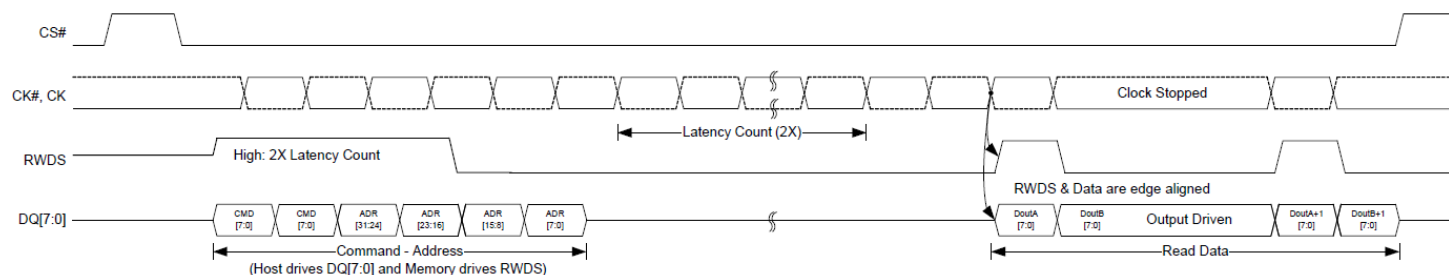
The Active Clock Stop mode reduces device interface energy consumption to the ICC6 level during the data transfer portion of a read or write operation. The device automatically enables this mode when clock remains stable for $t_{ACC} + 30$ ns. While in Active Clock Stop mode, read data is latched and always driven onto the data bus.

Active Clock Stop mode helps reduce current consumption when the host system clock has stopped to pause the data transfer. Even though CS# may be LOW throughout these extended data transfer cycles, the memory device host interface will go into the Active Clock Stop current level at $t_{ACC} + 30$ ns. This allows the device to transition into a lower current mode if the data transfer is stalled.

Active read or write current will resume once the data transfer is restarted with a toggling clock. The Active Clock Stop mode must not be used in violation of the t_{CSM} limit. CS# must go HIGH before t_{CSM} is violated.

Clock can be stopped during any portion of the active transaction as long as it is in the LOW state. Note that it is recommended to avoid stopping the clock during register access

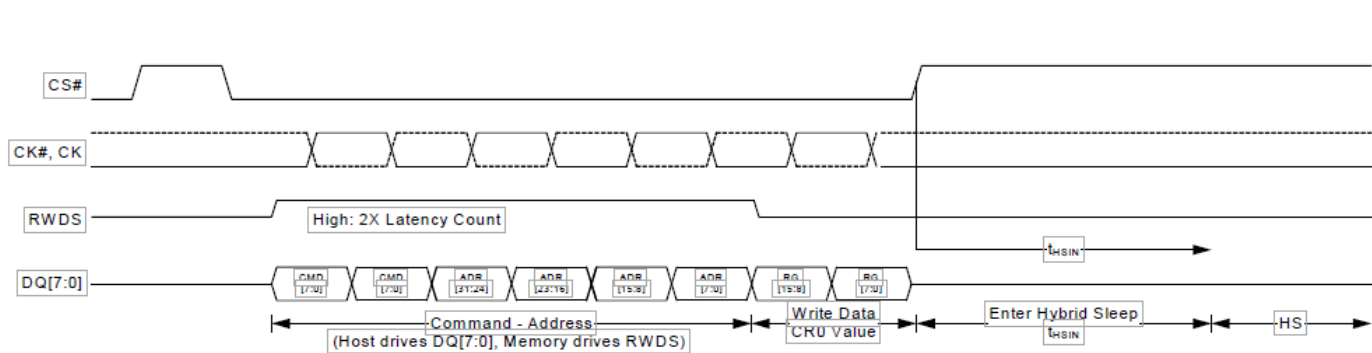
Figure 6.1 Active clock stop during read transaction (DDR)



6.1.3 Hybrid sleep

In the hybrid sleep (HS) state, the current consumption is reduced (I_{HS}). HS state is entered by writing '1' to CR1[5]. The device reduces power within t_{HSIN} time. The data in memory space and register space is retained during HS state. Bringing CS# LOW will cause the device to exit HS state and reset CR1[5] to '0'. Also, POR or a hardware reset will cause the device to exit hybrid sleep state. Note that a POR or a hardware reset disables refresh where the memory array data can potentially get lost. Returning to STANDBY state requires t_{EXTHS} time. Following the exit from HS due to any of these events, the device is in the same state as entering hybrid state.

Figure 6.2 Enter HS transaction



Note:

1. Latency Count is not applicable during the Register Write. The register write data byte immediately follows the last CA byte (zero clock latency)

Figure 6.3 Exit HS transaction

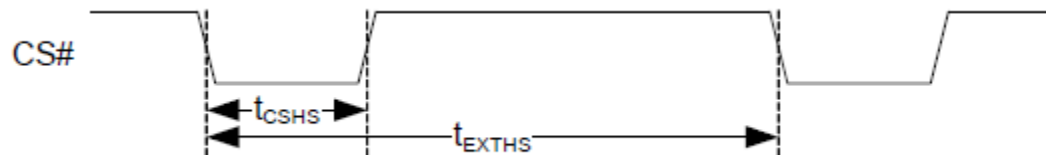


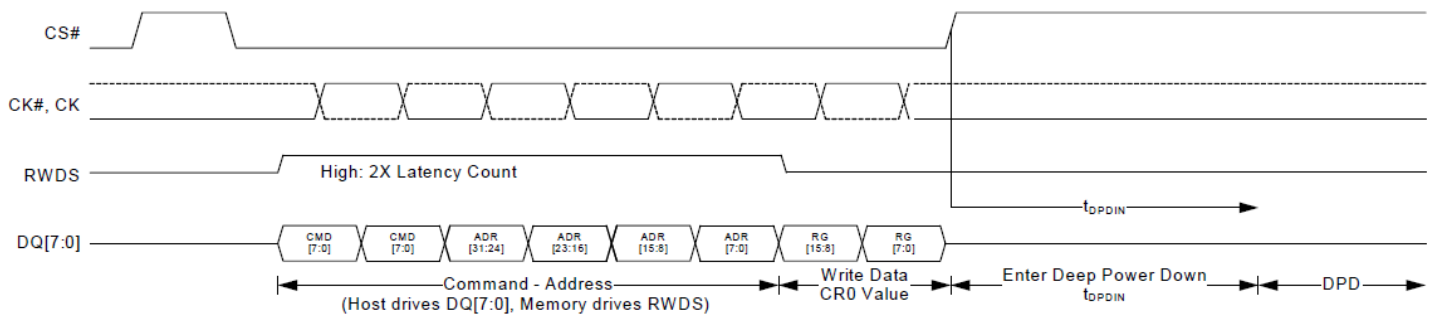
Table 6.1 Hybrid sleep timing parameters

Paramet	Description	Min	Max	Unit
t_{HSIN}	Hybrid sleep CR1[5] = 1 register write to enter HS power level	-	3	us
t_{CSHS}	CS# pulse width to exit HS	60	3000	ns
t_{EXTHS}	CS# exit hybrid sleep to standby wakeup time	-	100	us

6.1.4 Deep power down

In the hybrid sleep (HS) state, the current consumption is driven to the lowest possible level (I_{DPD}). DPD state is entered by writing '0' to CR0[15]. The device reduces power within t_{DPDIN} time and all refresh operations stop. The data in memory space is lost, (becomes invalid without refresh) during DPD state. Driving CS# LOW then HIGH will cause the device to exit DPD state. Also, POR or a hardware reset will cause the device to exit DPD state. Returning to STANDBY state requires t_{EXTDPD} time. Returning to STANDBY state following a POR requires t_{VCS} time, as with any other POR. Following the exit from DPD due to any of these events, the device is in the same states as following POR.

Figure 6.4 Enter DPD transaction



Note:

1. Latency Count is not applicable during the Register Write. The register write data byte immediately follows the last CA byte (zero clock latency)

Figure 6.5 Exit DPD transaction

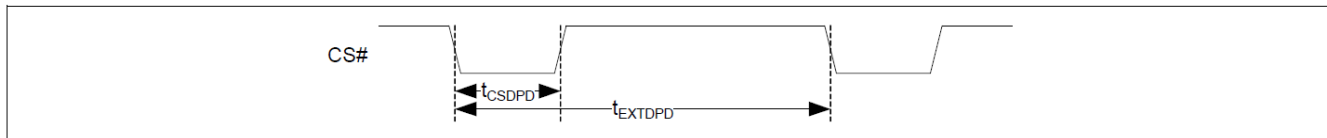


Table 6.2 Deep power down timing parameter

Paramet	Description	Min	Max	Unit
t_{DPDIN}	Deep power down CR0[15] = 0 register write to DPD power level	-	3	us
t_{CSDPD}	CS# pulse width to exit DPD	200	3000	ns
t_{EXTDPD}	CS# exit deep power down to standby wakeup time	-	150	us

7. Interface States

Table 7.1 describes the required value of each signal for each interface state.

Table 7.1 Interface States

Interface State	V_{CC} / V_{CCQ}	CS#	CK, CK#	DQ[7:0]	RWDS	RESET#
Power-Off	$< V_{LKO}$	X	X	HIGH-Z	HIGH-Z	X
Power-On (Cold) Reset	$\geq V_{CC} / V_{CCQ} \text{ min}$	X	X	HIGH-Z	HIGH-Z	X
Hardware (Warm) Reset	$\geq V_{CC} / V_{CCQ} \text{ min}$	X	X	HIGH-Z	HIGH-Z	L
Interface Standby	$\geq V_{CC} / V_{CCQ} \text{ min}$	H	X	HIGH-Z	HIGH-Z	H
CA	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	T	Master Output Valid	Y	H
Read Initial Access Latency (data bus turn around period)	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	T	HIGH-Z	L	H
Write Initial Access Latency (RWDS turn around period)	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	T	HIGH-Z	HIGH-Z	H
Read data transfer	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	T	Slave Output Valid	Slave Output Valid Z or T	H
Write data transfer with Initial Latency	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	T	Master Output Valid	Master Output Valid X or T	H
Write data transfer without Initial Latency ⁽¹⁾	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	T	Master Output Valid	Slave Output L or HIGH-Z	H
Active Clock Stop	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	Idle	Master or Slave Output Valid or HIGH-Z	Y	H
Deep Power Down	$\geq V_{CC} / V_{CCQ} \text{ min}$	L	X or T	HIGH-Z	HIGH-Z	H
Hybrid sleep	$\geq V_{CC} / V_{CCQ} \text{ min}$	H	X or T	HIGH-Z	HIGH-Z	H

Legend

L = V_{IL} , H = V_{IH}

X = either V_{IL} or V_{IH}

Y = either V_{IL} or V_{IH} or V_{OL} or V_{OH}

Z = either V_{OL} or V_{OH}

L/H = rising edge

H/L = falling edge

T = Toggling during information transfer

Idle = CK is LOW and CK# is HIGH.

Valid = all bus signals have stable L or H level

Notes

- Writes without initial latency (with zero initial latency), do not have a turn around period for RWDS. The HyperRAM device will always drive RWDS during the CA period to indicate whether extended latency is required. Since master write data immediately follows the CA period the HyperRAM device may continue to drive RWDS LOW or may take RWDS to HIGH-Z. The master must not drive RWDS during Writes with zero latency. Writes with zero latency do not use RWDS as a data mask function. All write data are written.

8. POWER-UP/POWER-DOWN

The device utilizes an 8-bit command register. Refer to Table 8.1. Command Set for details on commands and command codes. All commands, addresses, and data are shifted in with the most significant bit (MSB) first on Serial Data Input (SI) or Serial Data IOs (IO0, IO1, IO2, IO3). The input data on SI or IOs is latched on the rising edge of Serial Clock (SCK) for normal mode and both of rising and falling edges for DTR mode after Chip Select (CS#) is driven low (V_{IL}). Every command sequence starts with a one-byte command code and is followed by address bytes, data bytes, or both address bytes and data bytes, depending on the type of command. CS# must be driven high (V_{IH}) after the last bit of the command sequence has been shifted in to end the operation.

8.1 Power-Up Initialization

HyperRAM products include an on-chip voltage sensor used to launch the power-up initialization process. V_{CC} and V_{CCQ} must be applied simultaneously. When the power supply reaches a stable level at or above $V_{CC}(\min)$, the device will require t_{VCS} time to complete its self-initialization process.

The device must not be selected during power-up. CS# must follow the voltage applied on V_{CCQ} until $V_{CC}(\min)$ is reached during power-up, and then CS# must remain high for a further delay of t_{VCS} . A simple pull-up resistor from V_{CCQ} to Chip Select (CS#) can be used to insure safe and proper power-up.

If RESET# is Low during power up, the device delays start of the t_{VCS} period until RESET# is High. The t_{VCS} period is used primarily to perform refresh operations on the DRAM array to initialize it.

When initialization is complete, the device is ready for normal operation.

Figure 8.1 Power-up with RESET# HIGH

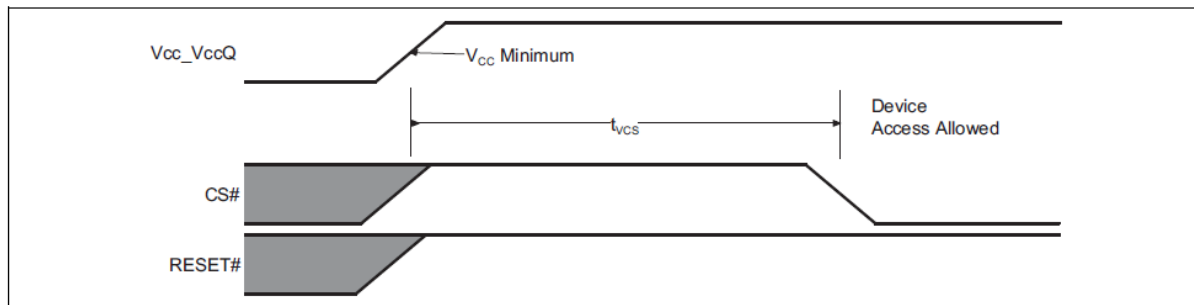


Figure 8.2 Power-up with RESET# LOW

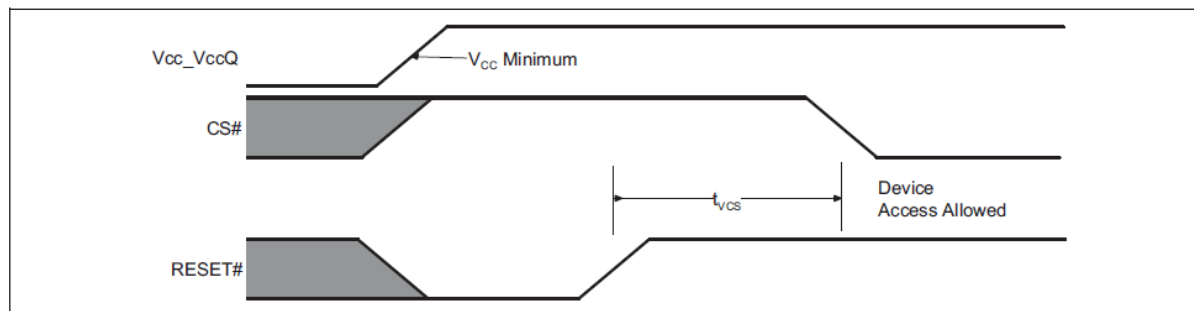


Table 8.1 Power Up and Reset Parameters

Parameter	Description	Min	Max	Unit
V_{CC}	1.8V V_{CC} Power Supply	1.7	1.95	V
V_{CC}	3V V_{CC} Power Supply	2.7	3.6	V
t_{VCS}	V_{CC} and $V_{CCQ} \geq$ minimum and RESET# High to first access	–	150	μs

Notes:

1. Bus transactions (read and write) are not allowed during the power-up reset time (t_{VCS}).
2. V_{CCQ} must be the same voltage as V_{CC} .
3. V_{CC} ramp rate may be non-linear.

8.2 Power-Down

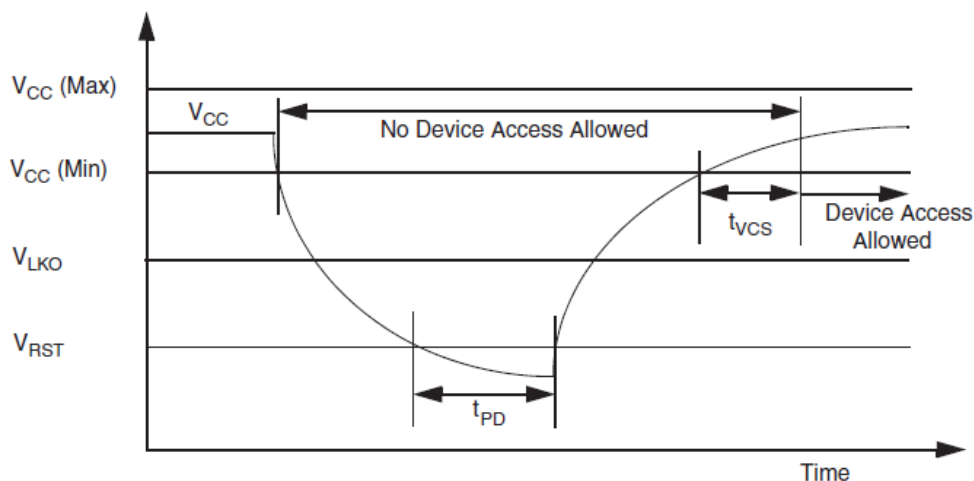
HyperRAM devices are considered to be powered-off when the core power supply (V_{CC}) drops below the V_{CC} Lock-Out voltage (V_{LKO}). During a power supply transition down to the VSS level, V_{CCQ} should remain less than or equal to V_{CC} .

At the V_{LKO} level, the HyperRAM device will have lost configuration or array data.

V_{CC} must always be greater than or equal to V_{CCQ} ($V_{CC} \geq V_{CCQ}$).

During Power-Down or voltage drops below V_{LKO} , the core power supply voltages must also drop below V_{CC} Reset (V_{RST}) for a Power Down period (t_{PD}) for the part to initialize correctly when the power supply again rises to V_{CC} minimum.

If during a voltage drop the V_{CC} stays above V_{LKO} the part will stay initialized and will work correctly when V_{CC} is again above V_{CC} minimum. If V_{CC} does not go below and remain below V_{RST} for greater than t_{PD} , then there is no assurance that the POR process will be performed. In this case, a hardware reset will be required ensure the HyperBus extended-IO device is properly initialized.

Figure 8.3 Power-Down or Voltage Drop


The following section describes HyperRAM device dependent aspects of power down specifications.

Table 8.2 Power Up and Reset Parameters (1.8V)

Symbol	Parameter	Min	Max	Unit
V_{CC}	V_{CC} Power Supply	1.7	1.95	V
V_{LKO}	V_{CC} Lock-out below which re-initialization is required	1.7	–	V
V_{RST}	V_{CC} Low Voltage needed to ensure initialization will occur	0.8	–	V
t_{PD}	Duration of $V_{CC} \leq V_{RST}$	30	–	μs

Note:

1. V_{CC} ramp rate can be non-linear.

Table 8.3 Power Up and Reset Parameters (3.0V)

Symbol	Parameter	Min	Max	Unit
V_{CC}	V_{CC} Power Supply	2.7	3.6	V
V_{LKO}	V_{CC} Lock-out below which re-initialization is required	2.4	–	V
V_{RST}	V_{CC} Low Voltage needed to ensure initialization will occur	0.8	–	V
t_{PD}	Duration of $V_{CC} \leq V_{RST}$	50	–	μs

Note:

1. V_{CC} ramp rate can be non-linear.

8.3 Hardware Reset

The RESET# input provides a hardware method of returning the device to the standby state.

During t_{RPH} the device will draw I_{CC5} current. If RESET# continues to be held Low beyond t_{RPH} , the device draws CMOS standby current (I_{CC4}). While RESET# is Low (during t_{RP}), and during t_{RPH} , bus transactions are not allowed.

A hardware reset will:

- cause the configuration registers to return to their default values,
- halt self-refresh operation while RESET# is low,

After RESET# returns High, the self-refresh operation will resume. Because self-refresh operation is stopped during RESET# Low, and the self-refresh row counter is reset to its default value, some rows may not be refreshed within the required array refresh interval per [Table 5.8, Array Refresh Interval per Temperature](#). This may result in the loss of DRAM array data during or immediately following a hardware reset. The host system should assume DRAM array data is lost after a hardware reset and reload any required data.

Figure 8.4 Hardware Reset Timing Diagram

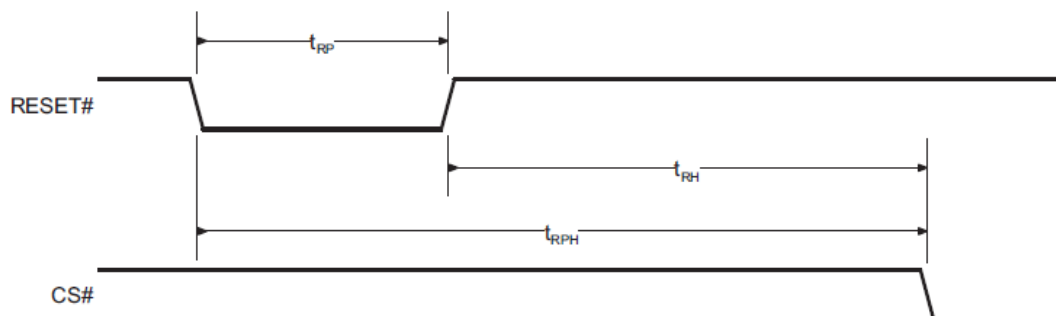


Table 8.4 Power Up and Reset Parameters

Parameter	Description	Min	Max	Unit
t_{RP}	RESET# Pulse Width	200	—	ns
t_{RH}	Time between RESET# (high) and CS# (low)	200	—	ns
t_{RPH}	RESET# Low to CS# Low	400	—	ns

9. ELECTRICAL CHARACTERISTICS

9.1 ABSOLUTE MAXIMUM RATINGS ⁽¹⁾

Parameter	Description
Storage Temperature	-65°C to +150°C
Ambient temperature with power applied	-65°C to +135°C
Voltage with Respect to Ground on All Pins ⁽¹⁾	-0.5V to V _{CC} + 0.5V
Voltage on V _{CC} supply relative to Ground	-0.5V to V _{CC} + 0.5V
Voltage on V _{CCQ} supply relative to Ground	-0.5V to V _{CCQ} + 0.5V
Output Short circuit current ⁽²⁾	100mA
Electrostatic Discharge Voltage (Human Body Model, ANSI/ESDA/JEDEC JS-001)	-2000V to +2000V

Notes:

1. Minimum DC voltage on input or I/O signal is -1.0V. During voltage transitions, input or I/O signals may undershoot VSS to -1.0V for periods of up to 20ns. Maximum DC voltage on input or I/O signals is VCC+1.0V. During voltage transitions, input or I/O signals may overshoot to VCC + 1.0V for periods up to 20ns.
2. No more than one output may be shorted to ground at a time. Duration of the short circuit should not be greater than one second.
3. Stresses above those listed under "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device or any other conditions above those indicated in the operational sections of the datasheet is not implied. Exposure of the device to absolute rating conditions for extended period may affect device reliability.

9.2 Latch up Characteristics

Description	Min	Max	Unit
Input voltage with respect to V _{SSQ} on all input only	- 1.0	V _{CCQ} + 1.0	V
Input voltage with respect to V _{SSQ} on all I/O connections	-1.0	V _{CCQ} + 1.0	V
V _{CCQ} Current	-100	+100	mA

9.3 Operating Ranges

Operating ranges define those limits between which the functionality of the device is guaranteed.

9.3.1 Temperature Ranges

Parameter	Symbol	Device	Spec		Unit
			Min	Max	
Ambient Temperature	T_A	Industrial (I)	-40	85	°C
		Automotive, Grade A1	-40	85	
		Automotive, Grade A2	-40	105	

9.3.2 Power Supply Voltages

1.8 V V_{CC} Power Supply	1.7v to 1.95V
3.0 V V_{CC} Power Supply	2.7V to 3.6V

9.3.3 Input Signal Overshoot

Minimum DC voltage on input or I/O signal is -1.0V for 1.8V device, and -2.0V for 3.0V device. During voltage transitions, input or I/O signals may undershoot V_{SS} to -1.0V or -2.0V for periods of up to 20ns. See figure 9.1. Maximum DC voltage on input or I/O signals is $V_{CC}+1.0V$ for 1.8V device, and $V_{CC}+2.0V$ for 3.0V device. During voltage transitions, input or I/O signals may overshoot to $V_{CC} + 1.0V$ or $V_{CC} + 2.0V$ for periods up to 20ns. See Figure 9.2.

Figure 9.1 Maximum Negative Overshoot Waveform for 1.8V device

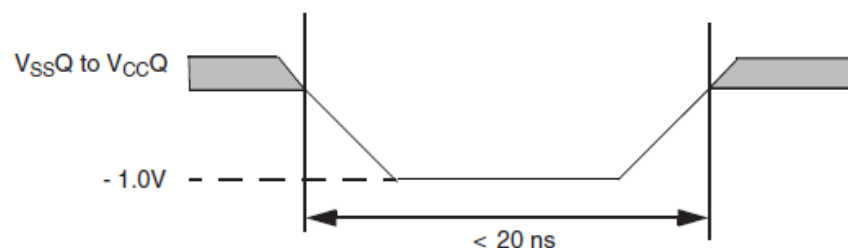
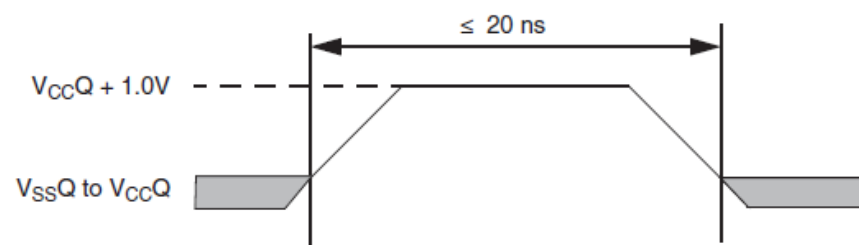


Figure 9.2 Maximum Positive Overshoot Waveform for 1.8V device



9.4 DC Characteristics

Table 9.1 DC Characteristics (CMOS Compatible)

Parameter	Description	Test Conditions		Value			Unit
				Min	Typ ⁽¹⁾	Max	
ILI1	Input Leakage Current 3.0 V Device Reset Signal High Only	V _{IN} = V _{SS} to V _{CC} , V _{CC} = V _{CC} max		-	-	+/-40	μA
ILI2	Input Leakage Current 1.8 V Device Reset Signal High Only	V _{IN} = V _{SS} to V _{CC} , V _{CC} = V _{CC} max		-	-	+/-20	
ILI3	Input Leakage Current 3.0 V Device Reset Signal Low Only ⁽²⁾	V _{IN} = V _{SS} to V _{CC} , V _{CC} = V _{CC} max		-	-	80	
ILI4	Input Leakage Current 1.8 V Device Reset Signal Low Only ⁽²⁾	V _{IN} = V _{SS} to V _{CC} , V _{CC} = V _{CC} max		-	-	80	
ICC1	V _{CC} Active Read Current	CS# = V _{SS} , @250 MHz, V _{CC} = 1.95V		-	70	80	mA
		CS# = V _{SS} , @200 MHz, V _{CC} = 3.6V		-	60	70	
ICC2	V _{CC} Active Write Current	CS# = V _{SS} , @250 MHz, V _{CC} = 1.95V		-	70	80	
		CS# = V _{SS} , @200 MHz, V _{CC} = 3.6V		-	60	70	
ICC4I	V _{CC} Standby Current (−40 °C to +85 °C)	CS# = V _{CC} , V _{CC} = V _{CC} max	Full array	-	-	3000	μA
			Top/Bot 1/2 array	-	-	2400	
			Top/Bot 1/4 array	-	-	2000	
			Top/Bot 1/8 array	-	-	1600	
I _{CC} 4IP	V _{CC} Standby Current (−40 °C to +105 °C)		Full array	-	-	3600	
			Top/Bot 1/2 array	-	-	3200	
			Top/Bot 1/4 array	-	-	2800	
			Top/Bot 1/8 array	-	-	2400	
ICC5	Reset Current	CS# = V _{IH} , RESET# = V _{IL} , V _{CC} = V _{CC} max		-	2	4	mA
ICC6	Active Clock Stop Current (−40 °C to +85 °C)	CS# = V _{IL} , RESET# = V _{IH} , V _{CC} = V _{CC} max		-	-	40	
	Active Clock Stop Current (−40 °C to +105 °C)	CS# = V _{IL} , RESET# = V _{IH} , V _{CC} = V _{CC} max		-		50	
ICC7	V _{CC} Current during power up	CS# = V _{CC} , V _{CC} = V _{CC} max, V _{CC} = V _{CCQ} = 1.95V or 3.6 ⁽¹⁾		-	-	160	
IDPD	Deep Power Down Current (−40 °C to +85 °C)	CS# = V _{CC} , V _{CC} = V _{CC} max		-	60	100	μA
	Deep Power Down Current (−40 °C to +105 °C)			-		160	

Table 9.1 DC Characteristics (Continued)

Parameter	Description	Test Conditions		Value			Unit
				Min	Typ ⁽¹⁾	Max	
IHS ⁽¹⁾	HS Sleep Current (–40 °C to +85 °C)	CS# = V _{CC} , V _{CC} = V _{CC} max	Full array	-	-	1600	μA
			Top/Bot 1/2 array	-	-	1200	
			Top/Bot 1/4 array	-	-	1000	
			Top/Bot 1/8 array	-	-	800	
	HS Sleep Current (–40 °C to +105 °C)		Full array	-	-	2000	
			Top/Bot 1/2 array	-	-	1600	
			Top/Bot 1/4 array	-	-	1200	
			Top/Bot 1/8 array	-	-	1000	
V _{IL}	Input Low Voltage	-	– 0.5	-	0.30 x V _{CC}	V	
V _{IH}	Input High Voltage	-	0.70 x V _{CC}	-	V _{CC} + 0.3	V	
V _{OL}	Output Low Voltage	I _{OL} = 100 μA for DQ [7:0]	-	-	0.15 x V _{CC}	V	
V _{OH}	Output High Voltage	I _{OH} = 100 μA for DQ [7:0]	0.85 x V _{CC}	-	–	V	

Notes:

1. Not 100% tested.
2. RESET# low initiates exit from DPD state or hybrid state and initiates the draw of I_{CC5} reset current, making I_{L1} during Reset# Low insignificant.

9.5 Capacitance Characteristics

Table 9.2 Capacitance Characteristics

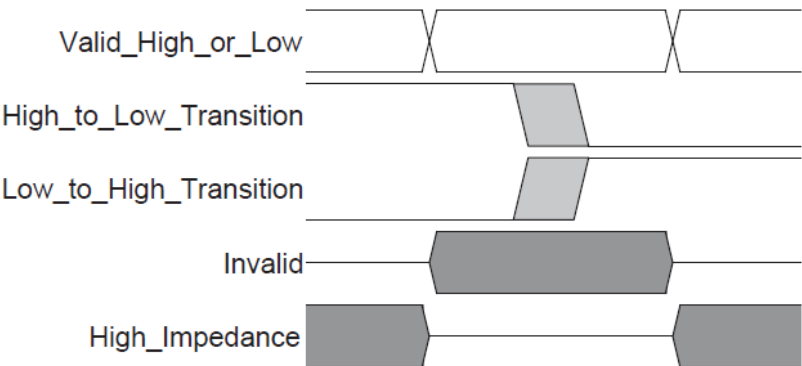
Description	Parameter	Min	Max	Unit
Input Capacitance (CK, CK#, CS#)	CI	6.0	9.0	pF
Delta Input Capacitance (CK, CK#)	CID	-	0.5	pF
Output Capacitance (RWDS)	CO	6.0	8.0	pF
IO Capacitance (DQx)	CIO	6.0	8.0	pF
IO Capacitance Delta (DQx)	CIOD	-	1.0	pF

Notes:

1. These values are guaranteed by design and are tested on a sample basis only.
2. Contact capacitance is measured according to JEP147 procedure for measuring capacitance using a vector network analyzer. V_{CC} , V_{CCQ} are applied and all other signals (except the signal under test) floating. DQ's should be in the high impedance state.
3. The capacitance values for the CK, RWDS and DQx signals must have similar capacitance values to allow for signal propagation time matching in the system. The capacitance value for CS# is not as critical because there are no critical timings between CS# going active (Low) and data being presented on the DQs bus.

10. Timing Specifications

10.1 Key to Switching Waveforms



10.2 AC Test Conditions

Figure 10.1 Test Setup

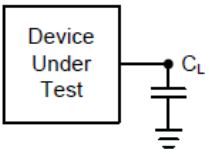


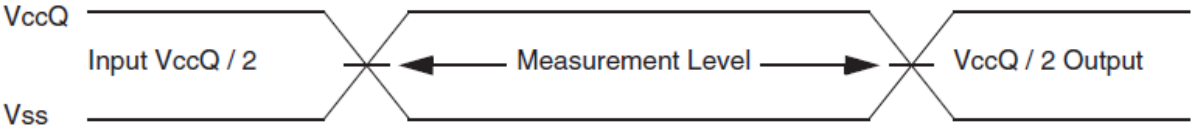
Table 10.1 Test Specification ⁽²⁾

Parameter	All Speeds	Unit
Output Load Capacitance, C_L	15	pF
Minimum Input Rise and Fall Slew Rates (1.8 V) ⁽¹⁾	1.13	V/ns
Minimum Input Rise and Fall Slew Rates (3.0 V) ⁽¹⁾	2.06	V/ns
Input Pulse Levels	0 - V_{CCQ}	V
Input timing measurement reference levels	$V_{CCQ}/2$	V
Output timing measurement reference levels	$V_{CCQ}/2$	V

Notes:

1. All AC timings assume this input slew rate.
2. Input and output timing is referenced to $V_{CCQ}/2$ or to the crossing of CK/CK#.

Figure 10.2 Input Waveforms and Measurement Levels ⁽¹⁾



Note:

1. Input timings for the differential CK/CK# pair are measured from clock crossings.

10.3 CLK Characteristics

Figure 10.3 Clock Characteristics

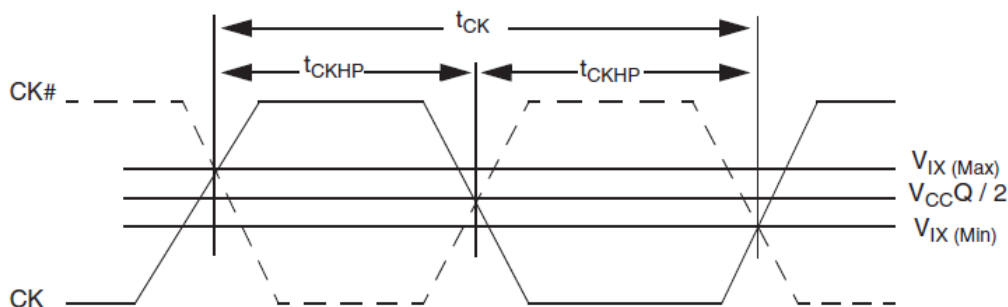


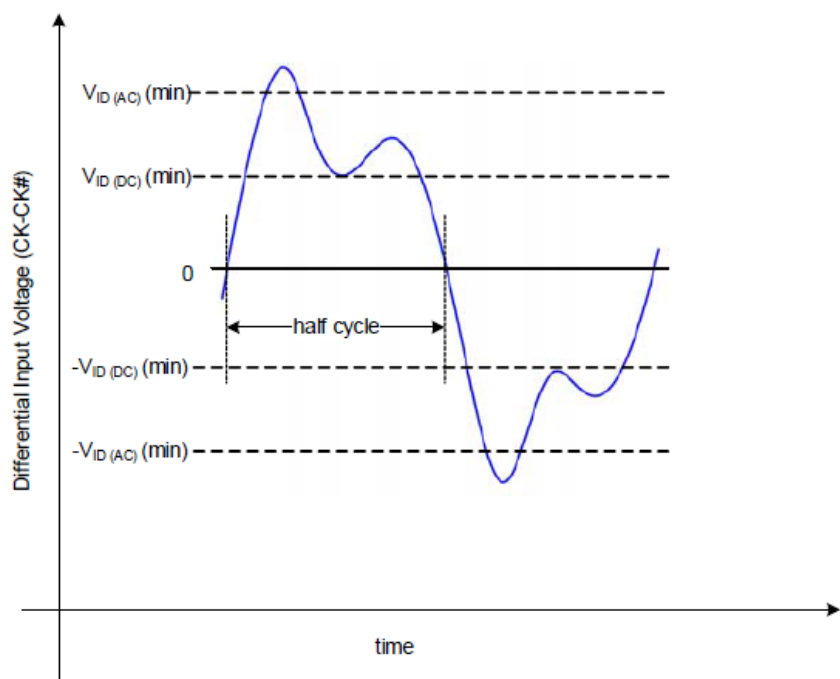
Table 10.2 Clock Timing ^(1,2,3)

Parameter	Symbol	250 MHz		200 MHz		166 MHz		Unit
		Min	Max	Min	Max	Min	Max	
CK Period	t_{CK}	4.0	-	5.0	-	6.0	-	ns
CK Half Period - Duty Cycle	t_{CKHP}	0.45	0.55	0.45	0.55	0.45	0.55	t_{CK}
CK Half Period at Frequency Min = $0.45t_{CK}$ Min Max = $0.55t_{CK}$ Min	t_{CKHP}	1.8	2.2	2.25	2.75	2.7	3.3	ns

Notes

1. Clock jitter of $\pm 5\%$ is permitted.
2. Minimum Frequency (Maximum t_{CK}) is dependent upon maximum CS# LOW time (t_{CSM}), Initial Latency and Burst Length.
3. CK and CK# input slew rate must be ≥ 1 V/ns (2 V/ns if measured differentially).

Figure 10.4 Differential clock (CK/CK#) input swing

Table 10.3 Clock AC/DC Electrical Characteristics^(1, 2)

Parameter	Symbol	Min	Max	Unit
DC Input Voltage	V_{IN}	-0.3	$V_{CCQ} + 0.3$	V
DC Input Differential Voltage	$V_{ID(DC)}$	$V_{CCQ} \times 0.4$	$V_{CCQ} + 0.6$	V
AC Input Differential Voltage	$V_{ID(AC)}$	$V_{CCQ} \times 0.6$	$V_{CCQ} + 0.6$	V
AC Differential Crossing Voltage	V_{IX}	$V_{CCQ} \times 0.4$	$V_{CCQ} \times 0.6$	V

Notes

1. V_{ID} is the magnitude of the difference between the input level on CK and the input level on CK#.
2. The value of V_{IX} is expected to equal $V_{CCQ}/2$ of the transmitting device and must track variations in the DC level of V_{CCQ} .

10.4 AC Characteristics

10.4.1 Read Transactions

Table 10.4 HyperRAM Specific Read Timing Parameters (1.8V)

Parameter	Symbol	250 MHz		200 MHz		Unit
		Min	M	Min	Max	
Chip Select High Between Transactions	t _{CSHI}	6	–	6	–	ns
HyperRAM Read-Write Recovery Time	t _{RWR}	35	–	35	–	ns
Chip Select Setup to next CK Rising Edge	t _{CSS}	4	–	4	–	ns
Data Strobe Valid	t _{DSV}	–	5	–	5	ns
Input Setup	t _{IS}	0.5	–	0.5	–	ns
Input Hold	t _{IH}	0.5	–	0.5	–	ns
HyperRAM Read Initial Access Time	t _{ACC}	28	–	35	–	ns
Clock to DQs Low Z	t _{DQLZ}	0	–	0	–	ns
CK transition to DQ Valid	t _{CKD}	1	5.0	1	5.0	ns
CK transition to DQ Invalid	t _{CKDI}	0	4.2	0	4.2	ns
Data Valid (t _{DV} min = t _{CKHP} min - t _{CKD} max + t _{CKDI} max)	t _{DV}	1.0	–	1.45	–	ns
CK transition to RWDS Valid	t _{CKDS}	1	5.0	1	5.0	ns
RWDS transition to DQ Valid	t _{DSS}	–0.4	+0.4	–0.4	+0.4	ns
RWDS transition to DQ Invalid	t _{DSH}	–0.4	+0.4	–0.4	+0.4	ns
Chip Select Hold After CK Falling Edge	t _{CSH}	0	–	0	–	ns
Chip Select Inactive to RWDS High-Z	t _{DSZ}	–	5	–	6	ns
Chip Select Inactive to DQ High-Z	t _{OZ}	–	5	–	6	ns
Refresh Time	t _{RFH}	28	–	35	–	ns
Chip Select Maximum Low Time	(- 40 °C to 85 °C)	t _{CSM}	–	4.0	–	μs
	(- 40 °C to 105 °C)		–	1.0	–	

Table 10.5 HyperRAM Specific Read Timing Parameters (3.0V)

Parameter		Symbol	200 MHz		166 MHz		Unit
			Min	M	Min	Max	
Chip Select High Between Transactions		t _{CSHI}	6	–	6	–	ns
HyperRAM Read-Write Recovery Time		t _{RWR}	35	–	36	–	ns
Chip Select Setup to next CK Rising Edge		t _{CSS}	4	–	3	–	ns
Data Strobe Valid		t _{DSV}	–	6.5	–	12	ns
Input Setup		t _{IS}	0.5	–	0.6	–	ns
Input Hold		t _{IH}	0.5	–	0.6	–	ns
HyperRAM Read Initial Access Time		t _{ACC}	35	–	36	–	ns
Clock to DQs Low Z		t _{DQLZ}	0	–	0	–	ns
CK transition to DQ Valid		t _{CKD}	1	6.5	1	7.0	ns
CK transition to DQ Invalid		t _{CKDI}	0.5	5.7	0.5	5.6	ns
Data Valid (t _{DV} min = t _{CKHP} min - t _{CKD} max + t _{CKDI} max)		t _{DV}	1.45	–	1.3	–	ns
CK transition to RWDS Valid		t _{CKDS}	1	6.5	1	7.0	ns
RWDS transition to DQ Valid		t _{DSS}	–0.4	+0.4	–0.4	+0.4	ns
RWDS transition to DQ Invalid		t _{DSH}	–0.4	+0.4	–0.4	+0.4	ns
Chip Select Hold After CK Falling Edge		t _{CSH}	0	–	0	–	ns
Chip Select Inactive to RWDS High-Z		t _{DSZ}	–	6.5	–	7.0	ns
Chip Select Inactive to DQ High-Z		t _{OZ}	–	6.5	–	7.0	ns
Refresh Time		t _{RFH}	35	–	36	–	ns
Chip Select Maximum Low Time	(- 40 °C to 85 °C)	t _{CSM}	–	4.0	–	4.0	μs
	(- 40 °C to 105 °C)		–	1.0	–	1.0	

Host drives DQ[7:0] and Memory drives RWDS

1. tCKD and tCKDI parameters define the beginning and end position of data valid.
2. tDSS and tDSH define how early or late DQ may transition relative to RWDS. This is a potential skew between the CK to DQ delay tCKD and CK to RWDS delay tCKDS.
3. Since DQ and RWDS are the same output types, the tCKD, tCKDI, and tCKDS values track together (vary by the same ratio)

10.4.2 Write Transactions

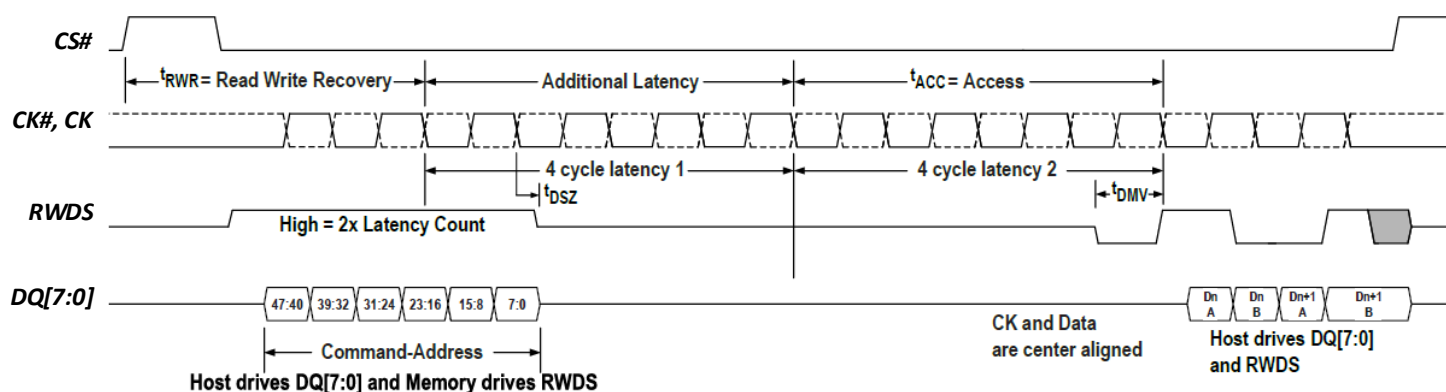
Table 10.6 HyperRAM Specific Write Timing Parameters (1.8V)

Parameter		Symbol	250 MHz		200 MHz		Unit
			Min	M	Min	Max	
Read-Write Recovery Time		t_{RWR}	35	—	35	—	ns
Access Time		t_{ACC}	28	—	35	—	ns
Refresh Time		t_{RFH}	28	—	35	—	ns
RWDS Data Mask Valid		t_{DMV}	0	—	0	—	ns
Chip Select Maximum Low Time	(–40 °C to 85 °C)	t_{CSM}	—	4.0	—	4.0	μ s
	(–40 °C to +105 °C)		—	1.0	—	1.0	

Table 10.7 HyperRAM Specific Write Timing Parameters (3.0V)

Parameter		Symbol	200 MHz		166MHz		Unit
			Min	M	Min	Max	
Read-Write Recovery Time		t_{RWR}	35	—	36	—	ns
Access Time		t_{ACC}	35	—	36	—	ns
Refresh Time		t_{RFH}	35	—	36	—	ns
RWDS Data Mask Valid		t_{DMV}	0	—	0	—	ns
Chip Select Maximum Low Time	(–40 °C to 85 °C)	t_{CSM}	—	4.0	—	4.0	μ s
	(–40 °C to +105 °C)		—	1.0	—	1.0	

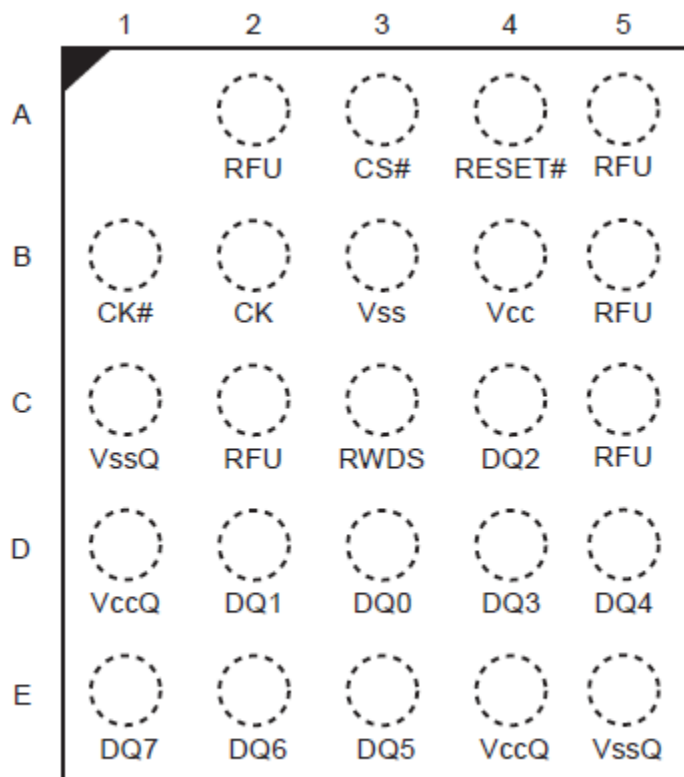
Figure 10.8 Write Timing Diagram — With Additional Latency



11. Physical Interface

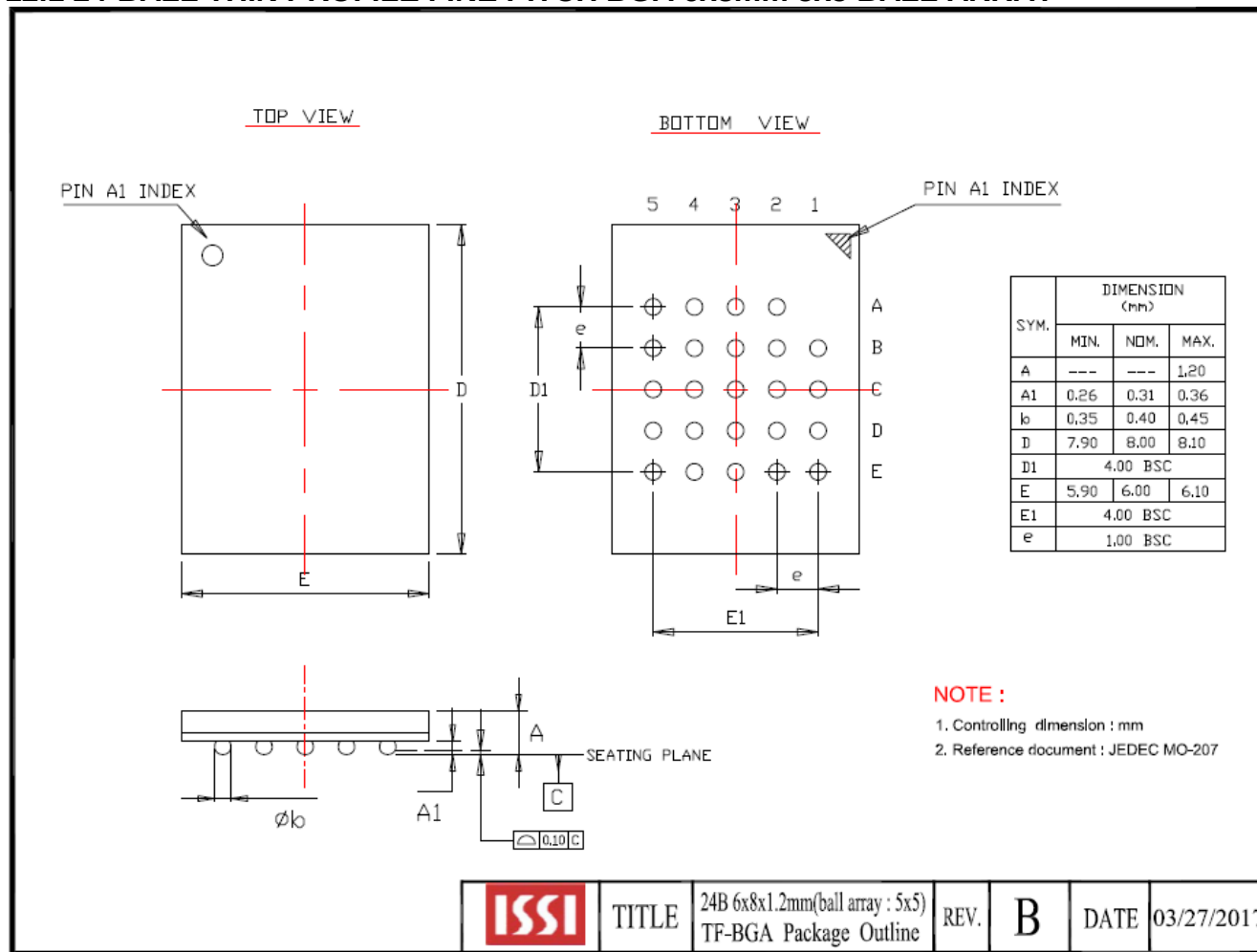
11.1 FBGA 24-Ball 5 x 5 Array Footprint

Figure 11.1 24-Ball FBGA, 6 x 8 mm, 5x5 Ball Footprint, Top View



12. Package Information

12.1 24-BALL THIN PROFILE FINE PITCH BGA 6x8mm 5x5 BALL ARRAY



13. ORDERING INFORMATION - Valid Part Numbers

IS67 WVH 128M8 E ALL - 250 B L I

TEMPERATURE RANGE

I = Industrial (-40°C to +85°C)
A1 = Automotive Grade (-40°C to +85°C)
A2 = Automotive Grade (-40°C to +105°C)

PACKAGING CONTENT

L = Green Package (RoHS Compliant, Halogen-Free) and TSCA Compliant

PACKAGE Type

B = 24-ball TFBGA (6x8mm) 5x5 ball array

Frequency

250 = 250MHz
200 = 200MHz
166 = 166MHz

Voltage

ALL = 1.8V
BLL = 3.0V

Die Revision

E = Revision E

Density/Org.

128M8 = 1Gb (128Mbx8)

Product Type

WVH = HyperRAM

BASE PART NUMBER

IS = Integrated Silicon Solution Inc.
66 = PSRAM
67 = Automotive PSRAM

Note:

1. Call Factory for other package options available

14. ORDERING TABLE

ALL: VDD = VDDQ = 1.7V~1.95V

Industrial Temperature Range: (-40 °C to +85 °C)

Config.	Frequency (MHz)	Order Part No.	Package
64Mx8	250	IS66WVH128M8EALL-250BLI	24-ball TFBGA, 5x5 Array
	200	IS66WVH128M8EALL-200BLI	24-ball TFBGA, 5x5 Array

Automotive A1 Temperature Range: (-40 °C to +85 °C)

Config.	Frequency (MHz)	Order Part No.	Package
64Mx8	250	IS66WVH128M8EALL-250BLA1	24-ball TFBGA, 5x5 Array
	200	IS66WVH128M8EALL-200BLA1	24-ball TFBGA, 5x5 Array

Automotive A2 Temperature Range: (-40 °C to +105 °C)

Config.	Frequency (MHz)	Order Part No.	Package
64Mx8	250	IS66WVH128M8EALL-250BLA2	24-ball TFBGA, 5x5 Array
	200	IS66WVH128M8EALL-200BLA2	24-ball TFBGA, 5x5 Array

BLL: VDD = VDDQ = 2.7V~3.6V

Industrial Temperature Range: (-40 °C to +85 °C)

Config.	Frequency (MHz)	Order Part No.	Package
64Mx8	200	IS66WVH128M8EBLL-200BLI	24-ball TFBGA, 5x5 Array
	166	IS66WVH128M8EBLL-166BLI	24-ball TFBGA, 5x5 Array

Automotive A1 Temperature Range: (-40 °C to +85 °C)

Config.	Frequency (MHz)	Order Part No.	Package
64Mx8	200	IS66WVH128M8EBLL-200BLA1	24-ball TFBGA, 5x5 Array
	166	IS66WVH128M8EBLL-166BLA1	24-ball TFBGA, 5x5 Array

Automotive A2 Temperature Range: (-40 °C to +105 °C)

Config.	Frequency (MHz)	Order Part No.	Package
64Mx8	200	IS66WVH128M8EBLL-200BLA2	24-ball TFBGA, 5x5 Array
	166	IS66WVH128M8EBLL-166BLA2	24-ball TFBGA, 5x5 Array